

Sixth BoS Meeting

July 21, 2023 (Friday) Seminar Hall, Department of Electronics and Communication Engineering

- M.Tech Electronics and Communication Engineering
- M.Tech VLSI and Embedded Systems
- Ph.D Electronics and Communication Engineering

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SRI MANAKULA VINAYAGAR ENGINEERING COLLEGE

(An Autonomous Institution) Puducherry - 605 107

6th PG - Board of Studies Meeting in the department of **Electronics and Communication Engineering**

for the Programme M.Tech – Electronics and Communication Engineering M.Tech – VLSI and Embedded Systems Ph.D – Electronics and Communication Engineering

> *Venue* Seminar Hall, Department of ECE Sri Manakula Vinayagar Engineering College Madagadipet, Puducherry – 605 107

> > Date & Time

21-07-2023 & 11.30 am

BOARD OF STUDIES MEETING

The Sixth Board of Studies meeting for PG and Research programs was held on July 21, 2023 at 11:30 AM in the Seminar Hall, Department of ECE, Sri Manakula Vinayagar Engineering College.

BoS Members

SI. No	Name of the Member	Designation
1	Dr. P. Raja Professor and Head, Department of ECE	Chairman
2	Dr. Gerardine Immaculate Mary Professor, Department of Embedded Systems, Vellore Institute of Technology (VIT), Vellore, Tamil Nadu, India	Expert Member (University Nominee)
3	Dr. N. Venkateswaran Professor, Department of ECE, SSN - College of Engineering, Kalavakkam, Tamil Nadu, India	Expert Member (Academic Council Nominee)
4	Dr. V. R. Vijayakumar Associate Professor & Head, Department of ECE, Anna University, Regional Campus, Coimbatore	Expert Member (Academic Council Nominee)
5	Mr. C. Gnanavel General Manager, Production and Technology, Lenovo India Ltd., Puducherry	Industry Member
6	Dr. V. Bharathi, Professor / ECE Specialization: Wireless Communication	Member

7	Dr. R. Ramya, Professor/ ECE	Member
	Specialization: ECE	Member
8	Dr. R. Kurinjimalar, Professor / ECE	Member
	Specialization: Mobile Satellite Communication	Member
9	Dr. J. Pradeep, Associate Professor / ECE	Member
	Specialization: Image Processing	Member
10	Prof. R. Ilaiyaraja, Assistant Professor / ECE	Member
	Specialization: VLSI Design	Member
11	Dr. T. Gayathri, Professor	Member
	Specialization: Mathematics	Member
12	Prof. K. Oudayakumar, Associate Professor	Member
	Specialization: Physics	Member
13	Dr. S. Savithri, Professor	Member
	Specialization: Chemistry	Member
14	Dr.D. Jaichithra, Associate Professor	Member
	Specialization: English	Member
4.5	Mr. G. Dharanidharan	
15	Birlasoft Limited, Old Mahabalipuram Road,	Alumni Member
	Chennai – 600096	

AGENDA OF THE MEETING

BoS /2023/PG/ECE 6.1

To review and confirm the minutes of fifth BoS meeting held on 17th September 2023

BoS /2023/PG/ECE 6.2

To discuss and approve Regulations 2023 (R-2023) for the M.Tech., Programmes for the students admitted from the academic year 2023-24

- M.Tech Electronics and Communication Engineering
- M.Tech VLSI and Embedded Systems

BoS /2023/PG/ECE 6.3

To discuss and approve curriculum structure and Syllabi for Semester I and II for M.Tech Electronics and Communication Engineering Programme under the Regulations R-2023

BoS /2023/PG/ECE 6.4

To discuss and approve curriculum structure and Syllabi for Semester I and II for M.Tech VLSI and Embedded Systems Programme under the Regulations R-2023

BoS /2023/PG/ECE 6.5

To appraise and approve the professional electives and employability enhancement courses chosen by the students under Regulations 2020

BoS /2023/PG/ECE 6.6

To discuss about the Internship course for PG programmes from the Academic Year 2021-22 onwards

BoS /2023/PG/ECE 6.7

To appraise and approve the list of eligible students called for personal interview for PhD programme in Electronics and Communication Engineering

BoS /2023/PG/ECE 6.8

Any other item with the permission of chair

MINUTES OF THE MEETING

Dr. P. Raja, Chairman of the Board of Studies (BoS), opened the Sixth BoS meeting for the M.Tech., and Research programs. He then proceeded to discuss the agenda items.

BoS / 2023 / PG/ ECE 6.1

To review and confirm the fifth BoS meeting minutes held on 17th September 2022

The fifth Board of Studies (BoS) meeting for M.Tech. in Electronics and Communication Engineering and M.Tech. in VLSI and Embedded Systems under Regulations 2020 was held on September 17, 2022. The minutes of the meeting were reviewed and confirmed.

BoS / 2023 / PG/ ECE 6.2

Approved and Confirmed

To discuss and approve Regulations 2023 (R-2023) for the M.Tech., Programmes for the students admitted from the academic year 2023-24

- M.Tech Electronics and Communication Engineering
- M.Tech VLSI and Embedded Systems

Members discussed the Regulations 2023 (R-2023) for the following M.Tech.. programs for students admitted from the academic year 2023-2024:

- M.Tech. in Electronics and Communication Engineering
- M.Tech. in VLSI and Embedded Systems

Approved and Recommended to the Academic Council

BoS / 2023 / PG/ ECE 6.3

To discuss and approve curriculum structure and Syllabi for Semester I and II for M.Tech., Electronics and Communication Engineering Programme under the Regulations R-2023

- In semester I, a High-Speed Electronics theory course has been introduced, with the suggestion from members to update the course content based on modern electronic devices.
- Semester II brought the introduction of a course on "Embedded Processors", with members proposing the inclusion of recent high-speed embedded processors in the syllabus.
- Additionally, members have recommended changing the course title of "Millimeter Wave Communication Networks" to "High-Frequency Communication System" in Semester II, with a syllabus containing 3 units of Millimeter wave communication and 2 units of optical communication.
- Members have expressed their appreciation for the Employability Enhancement Courses and Audit Courses offered in both semesters I and II under Regulations 2023.
- Members have discussed the professional elective course offered in both semesters I and II, as per Regulation 2023.

Approved with minor corrections and Recommended to the Academic Council

All the suggestions are considered and updated in the respective courses. The details are given in

Annexure – I (A): Curriculum of M. Tech – Electronics and Communication Engineering Annexure–I (B): Updated Syllabus M. Tech – Electronics and Communication Engineering

BoS / 2023 / PG/ ECE 6.4

To discuss and approve curriculum structure and Syllabi for Semester I and II for M.Tech VLSI and Embedded Systems Programme under the Regulations R-2023

- Members have suggested changing the course title to "Electronic Design Automation Tools" instead of "Digital System Design" course to provide an advanced level of learning in semester-I. They also suggested including recent automation tools in the syllabus to get more exposure at the industry level.
- The members suggested replacing the embedded networking course with the "Embedded Processors" course in semester 2 to provide knowledge on developing IoT models by utilizing these processors.
- The members appreciated the Employability Enhancement Courses and Audit Courses offered in Regulations 2023.
- Members have discussed the professional elective course offered in semesters 1 and 2 as per Regulation 2023.

Approved with minor corrections and Recommended to the Academic Council

All the suggestions are considered and updated in the respective courses. The details are given in

Annexure – II (A): Curriculum of M. Tech – VLSI and Embedded Systems Annexure–II (B): Updated Syllabus M. Tech – VLSI and Embedded Systems

BoS / 2023 / PG/ ECE 6.5

To appraise and approve the professional electives and employability enhancement courses chosen by the students under Regulations 2020

List of professional elective courses by the students from M.Tech - VLSI & ES

Semester	Course Code	Course Title
II	P20VEE210	Internet of Things
II	P20VEE212	Industrial Automation using PLC and SCADA

Noted and Approved

BoS / 2023 / PG/ ECE 6.6

To ratify the Internship course for PG programmes from the Academic Year 2021-22 onwards

The students from the M.Tech - ECE programme have completed the Internship

Enroll No.	Register No	Name of the Student	Company Name	Duration
211727	21PEC001	Divyadharshini P	Qmax Systems India Pvt. Ltd	1 months
210703	21PEC003	Nithya Valli.P	Qmax Systems India Pvt. Ltd	1 months

The students from the M.Tech- VLSI programme have completed the Internship

Enroll No.	Register No	Name of the Student	Company Name	Duration
210962	21PVE001	Balaji M	Idea Lab, SMVEC	1 months
210864	21PVE002	Nigithadharshini S	Qmax Systems India Pvt. Ltd	1 months
210797	21PVE003	Priyadharshni R	Idea Lab, SMVEC	1 months
211072	21PVE004	Sivaram Kumar R	Idea Lab, SMVEC	1 months
211062	21PVE005	Sivaraman S	Idea Lab, SMVEC	1 months

• Members esteemed the progress of the PG Internship.

Noted and Approved

BoS / 2023 / PG/ ECE 6.7

To appraise and approve the list of eligible students called for personal interview for PhD programme in Electronics and Communication Engineering

During the academic year 2022-2023, the Ph.D admission process was discussed by a member. In total, 70 candidates applied for the Ph.D programme, with 11 submitting applications specifically for Electronics and Communication Engineering. Out of those 11 candidates, 7 successfully passed the entrance examination and have been invited for a personal interview

List of eligible candidates called for personal interview

S. No	Name of the Candidate
1	D. Mary Getsy
2	R. Gayathri
3	J. Suganya
4	P. Srividdhya
5	B. Menaga
6	V. M. Navaneetha Krishnan
7	V. Logisvary

Approved and Recommended

BoS / 2023 / PG/ ECE 6.8

Any other item with the permission of chair

The syllabus is well-structured and covers advanced future technology topics. Additionally, the members encourage research scholars to publish their papers in reputable journals.

Dr. P. Raja, Chairman – BoS and Head of Department, Electronics and Communication Engineering, concluded the meeting at 12.30 pm with vote of thanks.

Dr. P. RAJA Board Chairman - ECE

Dr. GERARDINE IMMACULATE MARY Professor, Department of Embedded Systems, Vellore Institute of Technology (VIT), Vellore (Expert Member - University Nominee)

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Dr. N. VENKATESWARAN Professor, Department of ECE, SSN College of Engineering, Kalavakkam (Expert Member – AC Nominee)

C. Granand

Mr. C. GNANAVEL Manager, Production and Technology, Lenovo India Ltd., Puducherry (Industry. Member)

Dr. R. RAMYA Professor/ ECE (Member)

Dr. R. KURINJIMALAR Associate Professor / ECE (Member)

Prof. R. ILAIYARAJA, Assistant Professor / ECE (Member)

Prof. K. OUDAYAKUMAR Associate Professor / Physics (Member)

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Dr. D. JAICHITHRA Professor / English (Member)

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Dr. V. R. VIJAYAKUMAR Associate Professor & Head, Department of ECE, Anna University, Regional Campus, Coimbatore (Expert Member – AC Nominee)

Mr. DHARANIDHARAN. G Associated Functional Consultant, Birlasoft Limited, Chennai (Alumni Member)

Dr. V. BHARATHI Professor / ECE (Member)

Dr. J. PRADEÉP Associate Professor / ECE (Member)

Dr.T.GAYATHRI Professor / Mathematics (Member)

Dr.S.SAVITHIRI Professor / Chemistry (Member)

ANNEXURE – 1 (A): CURRICULUM M.Tech – Electronics and Communication Engineering



SRI MANAKULA VINAYAGAR ENGINEERING COLLEGE (An Autonomous Institution)

Puducherry

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

M.TECH.

ELECTRONICS AND COMMUNICATION ENGINEERING

(REGULATIONS-2023)

CURRICULUM & SYLLABI



VISION AND MISSION OF THE INSTITUTE

VISION

To be globally recognized for excellence in quality education, innovation and research for the transformation of lives to serve the society.

MISSION

M1: Quality Education	To provide comprehensive academic system that amalgamates the cutting edge-technologies with best practices
M2: Research and Innovation	To foster value-based research and innovation in collaboration with industries and institutions globally for creating intellectuals with new avenues
M3: Employability and Entrepreneurship	To inculcate the employability and entrepreneurial skills through value and skill-based training
M4: Ethical Values	To instill deep sense of human values by blending societal righteousness with academic professionalism for the growth of society

VISION AND MISSION OF THE DEPARTMENT

VISION

Facilitate academic excellence and research among Electronics and Communication Engineers to meet the Global needs with high competence and ethical professionalism

MISSION

M1: Academic	To impart learning skills to meet the global challenges in the field of						
Excellence	Electronics and Communication Engineering						
M2: Research and	To provide excellence in research and innovation through						
Innovation	multidisciplinary specialization						
M3: Employability	To enhance inter and intrapersonal skills among students to make						
	them employable and entrepreneurs						
M3: Employability and EntrepreneurshipTo enhance inter and intrapersonal skills among studer them employable and entrepreneurs	To inculcate the significance of human values and professional						
	skills to serve the society						

PROGRAMME OUT COMES (POs)

PO1: Exploration of Research:

An ability to independently carry out research/investigation and development work to solve practical problems.

PO2: Technical Skill:

An ability to write and present a substantial technical report/document.

PO3: Expertise in Academics:

Students should be able to demonstrate a degree of mastery over the area as per the specialization of the program. The mastery should be at a level higher than the requirements in the appropriate bachelor program.

PO4: Scholarship of Knowledge:

Acquire in-depth knowledge of specific discipline or professional area, including wider and global perspective, with an ability to discriminate, evaluate, analyze and synthesize existing and new knowledge, and integration of the same for enhancement of knowledge.

PO5: Usage of Modern Tools:

Create, select, learn and apply appropriate techniques, resources, and modern engineering and IT tools, including prediction and modelling, to complex engineering activities with an understanding of the limitations.

PO6: Ethical Practices and Social Responsibility:

Acquire professional and intellectual integrity, professional code of conduct, ethics of research and scholarship, consideration of the impact of research outcomes on professional practices and an understanding of responsibility to contribute to the community for sustainable development of society.

PROGRAM EDUCATIONAL OBJECTIVES (PEOs)

PEO1: Technical Knowledge

To develop intellectual combination of technology with modern electronics and communication systems through well-built technical acquaintance

PEO2: Leadership Skill

To endure changes and challenges in the areas of Electronics and Communication Engineering with good leadership skills.

PEO3: Research and Development

To identify the requisite of the nation, industry and come out with innovative solutions to maintain a sustainable position

PEO4: Professional Behavior

To promote competitive graduates global wise in Electronics and Communication Engineering

PROGRAM SPECIFIC OUTCOMES (PSOs)

PSO1: Technical Knowledge in Electronics and Communication Engineering

Ability to understand the technological advancements in the field of electronics and communication by using modern design tools and sub system end processes

PSO2: Competency in Electronics

Apply research ideas to offer solutions for extant problems in areas including signal processing, image processing, consumer electronics, VLSI, Embedded with given requirements

PSO3: Competency in Communication

Ability to develop and provide optimal solutions to subsystems like RF, baseband of modern communication systems and networks.

SI.			Ontonio	Pe	erio	ds	Onedite	Max. Marks		
No.	Course Code	Course Title	Category	L	Т	Ρ	Credits	CAM	ESM	Total
Theo	Theory									
1	P23MAT101	Probability and Stochastic Process	BS	2	2	0	3	40	60	100
2	P23ECT101	Advanced Digital Communication	PC	3	0	0	3	40	60	100
3	P23ECT102	Millimeter Wave Communication Networks	PC	3	0	0	3	40	60	100
4	P23ECT103	High Speed Electronics	PC	3	0	0	3	40	60	100
5	P23HSTC01	Research Methodology and IPR	HS	2	0	0	2	40	60	100
6	P23ECE1XX	Professional Elective - I	PE	3	0	0	3	40	60	100
Pract	tical	•								•
7	P23ECP101	Advanced Digital Communication Laboratory	PC	0	0	4	2	50	50	100
8	P23HSPC101	Technical Report Writing & Seminar	HS	0	0	4	2	100	0	100
Abili	Ability Enhancement Course									
9	P23ECC1XX	Certification Course – I	AEC	0	0	4	-	100	-	100
10	P23ACT10X	Audit Course - I	AEC	2	0	0	-	100	-	100
							21	590	410	1000

SEMESTER-I

SEMESTER-II

SI.	Course Code	ourse Code Course Title Cate		Periods			Credits	Max. Marks		
No.	Course Code	Course little	Category	L	Т	Ρ	Credits	CAM	ESM	Total
Theor	у									
1	P23VETC01	Advanced Digital System Design	PC	3	0	0	3	40	60	100
2	P23VETC02	Embedded Processors	PC	3	0	0	3	40	60	100
3	P23VETC03	Embedded System Design	PC	3	0	0	3	40	60	100
4	P23ECT204	Digital Image and Video Processing	PC	3	0	0	3	40	60	100
5	P23ECE2XX	Professional Elective - II	PE	3	0	0	3	40	60	100
6	P23ECEXX	Professional Elective - III	PE	3	0	0	3	40	60	100
Practi	ical									
7	P23ECP202	Digital Image and Video Processing laboratory	PC	0	0	4	2	50	50	100
8	P23HSPC202	Seminar on ICT-a hands on approach	HS	0	0	4	2	100	0	100
Abilit	y Enhancement	Course								
10	P23ECC2XX	Certification Course – II	AEC	0	0	4	-	100	-	100
11	P23ACT20X	Audit Course-II	AEC	2	0	0	-	100	-	100
	Total						22	590	410	1000

SEMESTER-III

SI.	Course Code	Course Title	Category L T	Periods		Cradita	Max. Marks			
No.	Course Code	Course fille		L	Т	Ρ	Credits	CAM	ESM	Total
Theor	ry									
1	P23ECE3XX	Professional Elective - IV	PE	3	0	0	3	40	60	100
2	P23ECE3XX	Professional Elective - V	PE	3	0	0	3	40	60	100
3	P23ECE3XX	Professional Elective - VI	PE	3	0	0	3	40	60	100
Proje	ct Work									
4	P23ECW301	Project Phase - I	PA	0	0	12	6	50	50	100
5	P23ECW302	Internship	PA	0	0	0	2	100	-	100
Mand	Mandatory Course									
6	P23ECC301	NPTEL / GIAN / MOOC	AEC	0	0	0	-	100	-	100
	Total					17	370	230	600	

SEMESTER-IV

SI. No. Course Code		Course Title	Catagony	Periods			Cradita	Max. Marks			
No.	Course Code Course The		Category	L	Т	Ρ	Credits	CAM	ESM	Total	
	Project Work										
1	1 P23ECW403 Project Phase - II PA 0 0 24						12	50	50	100	
	Total							50	50	100	

* Professional Elective Courses are to be selected from the list given in Annexure I

Ability Enhancement Courses are to be selected from the list given in Annexure II

** Audit Courses are to be selected from the list given in Annexure III

BS – Basic Science HS – Humanity Science PC – Professional Core PE – Professional Elective PA – Project Work C – Common Course AEC – Audit Course AEC – Ability Enhancement Course

Credit Distribution

Semester- I Semester - II		Semester - III	Semester - IV	Total	
21	22	17	12	72	

Total number of credits required to complete	70 and 140
M.Tech in Electronics and Communication Engineering	72 credits

Annexure – A

PROFESSIONAL ELECTIVE COURSES

		-I (Offered in Semester I)
SI. No.	Course Code	Course Title
1	P23ECE101	Advanced Microprocessor and Interfacing
2	P23ECE102	Image Processing and Recognition
3	P23ECE103	MIMO Systems
4	P23ECE104	Optical Communication and Networking
5	P23ECE105	Wireless Sensor Networks and its applications
Profes	sional Elective	- II (Offered in Semester II)
SI. No	Course Code	Course Title
1	P23VEEC01	Design of Analog and Mixed VLSI Circuits
2	P23VEEC02	Internet of Things and its Implementation
3	P23ECE206	Advanced Satellite Communication
4	P23ECE207	Mobile Communication System
5	P23ECE208	Statistical Information Processing
Profes	sional Elective	-III (Offered in Semester II)
SI. No	Course Code	Course Title
1	P23VEEC03	System on Chip Design
2	P23ECE309	Advanced Communication Network
3	P23ECE310	Advanced Radiation Systems
4	P23ECE311	Embedded Networking and Automation of Electrical System
5	P23ECE312	Industrial Electronics
Profes	sional Elective-	IV (Offered in Semester III)
SI. No	Course Code	Course Title
1	P23VEEC04	Real Time Operating System
2	P23VEEC05	Cloud computing and Distributed System
3	P23ECE313	Automotive Embedded System
4	P23ECE314	Information and Network Security
5	P23ECE315	RF and Microwave Circuit Design
Profes	sional Elective	-V (Offered in Semester III)
SI. No	Course Code	Course Title
1	P23VEEC06	Edge Computing
2	P23ECE316	Cognitive Radio Technology
3	P23ECE417	Embedded Computing
4	P23ECE418	Markov Chains and Queuing Systems
5	P23ECE419	Modeling and Simulation of Wireless Communication Systems
Profes	sional Elective-	VI (Offered in Semester III)
SI. No	Course Code	Course Title
1	P23ECE420	Unmanned Aerial Vehicle
2	P23ECE421	Free Space Optical Networks
3	P23ECE422	Intelligent Control and Automation
4	P23ECE423	Multicarrier Wireless Communication
	=======	

Annexure – B

ABILITY ENHANCEMENT COURSES

S. No	Course Code	Course Title	Certified By
1	P23XXCX01	Adobe Photoshop	Adobe
2	P23XXCX02	Adobe Animate	Adobe
3	P23XXCX03	Adobe Dreamweaver	Adobe
4	P23XXCX04	Adobe After Effects	Adobe
5	P23XXCX05	Adobe Illustrator	Adobe
6	P23XXCX06	Adobe InDesign	Adobe
7	P23XXCX07	Autodesk AutoCAD -ACU	Autodesk
8	P23XXCX08	Autodesk Inventor - ACU	Autodesk
9	P23XXCX09	Autodesk Revit - ACU	Autodesk
10	P23XXCX10	Autodesk Fusion 360 - ACU	Autodesk
11	P23XXCX11	Autodesk 3ds Max - ACU	Autodesk
12	P23XXCX12	Autodesk Maya - ACU	Autodesk
13	P23XXCX13	Cloud Security Foundations	AWS
14	P23XXCX14	Cloud Computing Architecture	AWS
15	P23XXCX15	Cloud Foundation	AWS
16	P23XXCX16	Cloud Practitioner	AWS
17	P23XXCX17	Cloud Solution Architect	AWS
18	P23XXCX18	Data Engineering	AWS
19	P23XXCX19	Machine Learning Foundation	AWS
20	P23XXCX20	Robotic Process Automation / Medical Robotics	Blue Prism
21	P23XXCX21	Advance Programming Using C	CISCO
22	P23XXCX22	Advance Programming Using C ++	CISCO
23	P23XXCX23	C Programming	CISCO
24	P23XXCX24	C++ Programming	CISCO
25	P23XXCX25	CCNP Enterprise: Advanced Routing	CISCO
26	P23XXCX26	CCNP Enterprise: Core Networking	CISCO
27	P23XXCX27	Cisco Certified Network Associate - Level 2	CISCO
28	P23XXCX28	Cisco Certified Network Associate- Level 1	CISCO
29	P23XXCX29	Cisco Certified Network Associate- Level 3	CISCO
30	P23XXCX30	Fundamentals of Internet of Things	CISCO
31	P23XXCX31	Internet of Things / Solar and Smart Energy System with IoT	CISCO
32	P23XXCX32	Java Script Programming	CISCO
33	P23XXCX33	NGD Linux Essentials	CISCO
34	P23XXCX34	NGD Linux I	CISCO
35	P23XXCX35	NGD Linux II	CISCO
36	P23XXCX36	Advance Java Programming	Ethnotech
37	P23XXCX37	Android Programming / Android Medical App Development	Ethnotech
38	P23XXCX38	Angular JS	Ethnotech
39	P23XXCX39	Catia	Ethnotech
40	P23XXCX40	Communication Skills for Business	Ethnotech
41	P23XXCX41	Coral Draw	Ethnotech
42	P23XXCX42	Data Science Using R	Ethnotech
43	P23XXCX43	Digital Marketing	Ethnotech
44	P23XXCX44	Embedded System Using C	Ethnotech

S. No	Course Code	Course Title	Certified By
45	P23XXCX45	Embedded System with IoT / Arduino	Ethnotech
46	P23XXCX46	English for IT	Ethnotech
47	P23XXCX47	Plaxis	Ethnotech
48	P23XXCX48	Sketch Up	Ethnotech
49	P23XXCX49	Financial Planning, Banking and Investment Management	Ethnotech
50	P23XXCX50	Foundation of Stock Market Investing	Ethnotech
51	P23XXCX51	Machine Learning / Machine Learning for Medical Diagnosis	Ethnotech
52	P23XXCX52	IOT Using Python	Ethnotech
53	P23XXCX53	Creo (Modelling & Simulation)	Ethnotech
54	P23XXCX54	Soft Skills, Verbal, Aptitude	Ethnotech
55	P23XXCX55	Software Testing	Ethnotech
56	P23XXCX56	MX-Road	Ethnotech
57	P23XXCX57	CLO 3D	Ethnotech
58	P23XXCX58	Solid works	Ethnotech
59	P23XXCX59	Staad Pro	Ethnotech
60	P23XXCX60	Total Station	Ethnotech
61	P23XXCX61	Hydraulic Automation	Festo
62	P23XXCX62	Industrial Automation	Festo
63	P23XXCX63	Pneumatics Automation	Festo
64	P23XXCX64	Agile Methodologies	IBM
65	P23XXCX65	Block Chain	IBM
66	P23XXCX66	Devops	IBM
67	P23XXCX67	Artificial Intelligence	ITS
68	P23XXCX68	Cloud Computing	ITS
69	P23XXCX69	Computational Thinking	ITS
70	P23XXCX70	Cyber Security	ITS
71	P23XXCX71	Data Analytics	ITS
72	P23XXCX72	Databases	ITS
73	P23XXCX73	Java Programming	ITS
74	P23XXCX74	Networking	ITS
75	P23XXCX75	Python Programming	ITS
76	P23XXCX76	Web Application Development (HTML, CSS, JS)	ITS
77	P23XXCX77	Network Security	ITS & Palo alto
78	P23XXCX78	MATLAB	MathWorks
79	P23XXCX79	Azure Fundamentals	Microsoft
80	P23XXCX80	Azure AI (AI-900)	Microsoft
81	P23XXCX81	Azure Data (DP -900)	Microsoft
82	P23XXCX82	Microsoft 365 Fundamentals (SS-900)	Microsoft
83	P23XXCX83	Microsoft Security, Compliance and Identity (SC-900)	Microsoft
84	P23XXCX84	Microsoft Power Platform (PI-900)	Microsoft
85	P23XXCX85	Microsoft Dynamics Fundamentals 365 – CRM	Microsoft
86	P23XXCX86	Microsoft Excel	Microsoft
87	P23XXCX87	Microsoft Excel Expert	Microsoft
88	P23XXCX88	Securities Market Foundation	NISM
89	P23XXCX89	Derivatives Equinity	NISM
90	P23XXCX90	Research Analyst	NISM
91	P23XXCX91	Portfolio Management Services	NISM
92	P23XXCX92	Cyber Security	Palo alto

S. No	Course Code	Course Title	Certified By
93	P23XXCX93	Cloud Security	Palo alto
94	P23XXCX94	PMI – Ready	PMI
95	P23XXCX95	Tally – GST & TDS	Tally
96	P23XXCX96	Advance Tally	Tally
97	P23XXCX97	Associate Artist	Unity
98	P23XXCX98	Certified Unity Programming	Unity
99	P23XXCX99	VR Development	Unity

Annexure- C

AUDIT COURSES

SI. No.	Course Code	Course Title		
1	P23ACTX01	English for Research Paper Writing		
2	P23ACTX02	Disaster Management		
3 P23ACTX03 Sanskrit for Technical Knowledge				
4	P23ACTX04	Value Education		
5	P23ACTX05	Constitution of India		
6	P23ACTX06	Pedagogy Studies		
7	P23ACTX07	Stress Management by Yoga		
8	P23ACTX08	Personality Development Through Life Enlightenment Skills		
9	P23ACTX09	Unnat Bharat Abhiyan		

ANNEXURE – 1 (B): UPDATED SYLLABUS

M.Tech – Electronics and Communication Engineering

Semester	Course Code	Course Title		
I	P23ECT103	High Speed Electronics		
II	P23VETC02	Embedded Processors		

Semester	Course Code	Course Title				
I	P23ECE101	Advanced Microprocessor and Interfacing				
II	P23VEEC02	Internet of Things and its Implementation				

Department		ECE	·····	nme: M		*****			
Semester		I						ter Exaı TE	т Туре
Course			Pe	eriods/W	'eek	Credit	edit Maximum M CAM ESE 40 60 BT M (Highe T, BJT	Marks	
Code		P23ECT103	L	Т	Р	С	CAM	ESE	TM
Course Name	Hi	gh Speed Electronics	3	0	0	3	40	60	100
Prerequisite									
	On cor	mpletion of the course, the	students w	ill be abl	e to				apping st Level
	CO1 Understand the concept of Semiconductor Material with its Characteristics								2
Course	CO2 To explain about homo junction and its characteristics in FET, BJT								2
Outcome	CO3 Differentiate homo-junction and hetero-junction Devices								2
	CO4	Apply knowledge of Advar	nced Devic	es in Hig	h-Speed	Applicati	on		2
	CO5 Understand various process of Fabrication and Characterization Techniques							2	
Unit-I	Semic	onductor Material Charac	taristics					Period	s. Uð
		ucture: Crystal structure of		semicon	ductors (′Si Ga∆s	InP) - e		
in periodic latti	ices - e	energy band diagram - carrie nermal and high field proper	er concent	ration an	d carrier				CO1
Unit-II	Homo	junction Device						Period	s: 09
		es (BJT and FET): Structure rtical expressions) - small si				n - I–V and	d C–V		CO2
Unit-III	MOS [Device						Period	s: 09
avalanche inje - structure - op and punch thre	ection - peratior pugh –	e - band diagram - operatio high field effects and break n - I–V and C–V characteris sub-threshold current -scal SFET - buried channel MOS	down; Het stics (analy ling down;	erojuncti tical expi Alternate	on Base ressions) e High k-	d MOSFE) - MOSFI dielectric	T: Band ET breal	diagran down	CO3
Unit-IV	Advan	ced Device						Period	s: 09
diagram - ope	ration -	ices: AlGaAs/ GaAs, InP an I–V and C–V characteristic netero-junction transistor for	s (analytic	al expres	ssions) -				CO4
	1	ation and Characterizatio						Period	s: 09
Crystal Growth and oxidization lithography teo techniques; Cl	h and V h techn chnique haracte	Vafer Preparation: Epitaxy - iiques - masking and lithogr es) - metallization - bipolar a prization Techniques: Four p eterization and DLTS	- diffusion raphy tech and MOS i	- ion imp niques (c ntegratio	optical, e n technic	-beam an ques - inte	d other a erface pa	eposition advance assivatio	d
Lecture Perio			Practica	al Period	ls: -	T	otal Per	iods: 45	l
Textbooks			I					_	
		Gupta and Amitava Das C	Gupta, "Se	micondu	ctor Dev	rices: Moo	deling ar	nd Techr	nology",
		all of India,2012.	ata # 14 - 1 - 1		`		lav av 1	0	00
2 1/1 S	ivadi '	"Introduction to Semicondu	ctor Mater	ais and I	Jevices"	John Wi	iev and	-ons 20	NN

- 2. M. S. Tyagi, "Introduction to Semiconductor Materials and Devices", John Wiley and Sons, 2008.
- 3. M. J. Madou, Fundamentals of Microfabrication, 2nd Edition, CRC Press, 2011.

4. P. Bhattacharya, Semiconductor Optoelectronics Devices, 2nd Edition, PHI, 2009

- 1. S. M. Sze, "Physics of Semiconductor Devices", 3rd edition, John Wiley and Sons, 2007.
- 2. J. Singh, "Semiconductor Devices: Basic Principles", John Wiley and Sons, 2007.
- 3. J. P. McKelvey, Introduction to Solid State and Semiconductor Physics, Harper and Row and John Weathe Hill.
- 4. Cheng T. Wang, Ed., Introduction to Semiconductor Technology: GaAs and Related Compounds, John Wiley & Sons, 1990.
- Donald A Neamen, Semiconductor Physics and Devices: Basic Principles, McGraw-Hill (1997) ISBN 0-256-24214-3

- 1. https://nptel.ac.in/courses/117104071/
- 2. https://cosmolearning.org/courses/high-speed-devices-circuits/
- 3. https://www.docsity.com/en/lecture-notes/subjects/high-speed-electron-devices/
- 4. https://www.researchgate.net/journal/International-Journal-of-High-Speed-Electronics-and-Systems-0129-1564
- 5. https://ieeexplore.ieee.org/document/6647520
- * TE Theory Exam, LE Lab Exam

COs/POs/PSOs Mapping

	Program Outcomes (POs)					Program Specific Outcomes (PSOs)			
COs	PO1	PO2	PO3	PO4	PO5	PO6	PSO1	PSO2	PSO3
1	2	1	1	1	-	-	1	-	3
2	2	1	2	1	-	-	1	-	3
3	2	1	2	1	-	-	1	-	3
4	2	2	2	1	-	-	1	-	3
5	2	2	1	1	-	-	1	3	3

Correlation Level: 1 - Low, 2 - Medium, 3 – High

Evaluation Method

		Contir	nuous Asse	ssment Marks (CAM)	End Semester	Total
Assessment	CAT	CAT	Model	Assignment*	Attendance	Examination (ESE)	Marks
	1	2	Exam	Assignment	Attenuance	Marks	iviai KS
Marks	1	10		10	5	60	100

Semester	*	ECE		<u> </u>		Tech. E	·······			
Concort		II		Cοι	urse Cat PC	egory:	*Enc	I Semes	ter Exar TE	n Type:
Course		P23VETC02		Periods/Week			Cred	it Max	ximum N	/larks
Code		FZ3VEICUZ	•	L	Т	Р	С	CAM	ESE	ТМ
Course Name		mbedded Proce		3	0	0	3	40	60	100
.		ch ECE and M.T	ech – VLS	I & ES)						
Prerequisite		mpletion of the co	urse, the st	udents w	vill be abl	e to			(H	/lapping ighest evel)
-	CO1	Analyze the archi	ectures of	different	Embedd	ed Proce	ssors			3
Course Outcome	CO2	Identify an approp communication	priate on chi	ip periph	erals for	serial an	d paralle	el		2
	CO3	Examine the func	tions of AR	M proces	ssors					3
	CO4	Develop real time	application	is using <i>i</i>	ARM pro	cessors				3
	CO5	Develop a firmwa	re for embe	edded ap	plication	S				3
S	Introd	uction to Embed	ded Proce	ssors					Perio	ods: 9
Jnit-II Memory - Inte	Embe	n, Models of Simp <mark>dded Processor</mark> s				action, S	OC Star	ndard Bus	······	
2C interface, Jnit-III Architecture o operation - D/ Cemperature s Jnit-IV nterfacing the	e - Con Analog ARM f ARM f ARM A and sensing Real V e peript	- I/O Ports-Timer pare Mode-PWM Comparator, Ana Processor Controller – Reg A/D converter, se g, Light sensing, Ir Vorld Interfacing merals to LPC2148 SD card interface	s & Real T Mode - Se log interfac isters, Pipe nsors, actu troduction Using ARI :: GSM and	ime Cloo erial com eline orga ators an to Intern M Proce I GPS us	ck (RTC) municati data acq anization d their in et of Thir ssor sing UAR	on modul uisition. 3 stage terfacing ngs, smar T, on-chi	& 5 sta – Case t home of	RT - SP ge, Thun study- D concepts using inte	P module I interfac Perio b mode igital clo Perio	e - CO2 ods: 9 of ck, CO3 ods: 9 C),
2C interface, Unit-III Architecture o operation - D/ Temperature s Unit-IV Interfacing the EEPROM usir	 Con Analog ARM I ARM I ARM I A and Sensing Real V Periphog I2C, ARM I 	pare Mode-PWM Comparator, Ana Processor Controller – Reg A/D converter, se g, Light sensing, Ir Vorld Interfacing herals to LPC2148 SD card interface Cortex Processo	s & Real T Mode - Se log interfac isters, Pipe nsors, actu troduction Using ARI :: GSM and using SPI,	ime Clor erial com sing and eline orga ators an to Intern M Proce GPS us on-chip	ck (RTC) municati data acq anization d their in et of Thir ssor Sing UAR DAC for	on modul uisition. 3 stage terfacing ngs, smar T, on-chi waveforn	& 5 sta – Case t home α p ADC ι n genera	RT - SP ge, Thun study- D concepts using inte ation.	P module I interfac Peric nb mode igital clo Peric Peric	s - e -CO2 ods: 9 of ck,CO3 ods: 9 C), CO4 ods: 9
2C interface, Unit-III Architecture o operation - D/ Temperature s Unit-IV Interfacing the EEPROM usir Unit-V Introduction to system desig applications, Firmware dev comparison	 constant Analog ARM I ARM I A and sensing Real V periphag I2C, ARM I ARM I ARM I ARM I 	pare Mode-PWM Comparator, Ana Processor Controller – Reg A/D converter, se g, Light sensing, Ir Vorld Interfacing herals to LPC2148 SD card interface Cortex Processor CORTEX series, RTEX A, CORTE of operating systement for ARM Cort	s & Real T Mode - Se log interfac isters, Pipe nsors, actu troduction Using ARI : GSM and using SPI, rs mprovement EX M, CO em in deve ex, Survey	ime Clor erial com sing and eline orga ators an to Intern M Proce I GPS us on-chip nt over co RTEX R eloping of COF	ck (RTC) municati data acq anization d their in et of Thir ssor sing UAR DAC for classical s complex RTEX MS	on modul uisition. 3 stage terfacing ngs, smar T, on-chi waveforn series an sors seri applicat based	& 5 sta – Case t home of p ADC u n genera d advan es, vers ions in controlle	ge, Thun study- D concepts using inte ation. tages for sions, fe embedd ers, its fe	Peric Peric Peric Peric Peric Peric Peric embedd atures a ed syste eatures a	s - e -CO2 ods: 9 of ck, CO3 ods: 9 C), CO4 ods: 9 led ind em, CO5 ind
I2C interface, Unit-III Architecture o operation - D/ Temperature s Unit-IV Interfacing the EEPROM usir Unit-V Introduction to system desig applications,	 constant Analog ARM I ARM I A and sensing Real V periphag I2C, ARM I ARM I ARM I ARM I ARM I 	pare Mode-PWM Comparator, Ana Processor Controller – Reg A/D converter, se g, Light sensing, Ir Vorld Interfacing herals to LPC2148 SD card interface Cortex Processor CORTEX series, RTEX A, CORTE of operating systement for ARM Cort	s & Real T Mode - Se log interfac isters, Pipe nsors, actu itroduction Using ARI : GSM and using SPI, s mprovement X M, CO em in deve	ime Clor erial com sing and eline orga ators an to Intern M Proce I GPS us on-chip nt over co RTEX R eloping of COF	ck (RTC) municati data acq anization d their in et of Thir ssor sing UAR DAC for classical s complex RTEX MS	on modul uisition. 3 stage terfacing ngs, smar T, on-chi waveforn series an sors seri applicat	& 5 sta – Case t home of p ADC u n genera d advan es, vers ions in controlle	ge, Thun study- D concepts using inte ation. tages for sions, fe embedd ers, its fe	P module I interfac Peric igital clo Peric errupt (VII Peric embedd atures a ed syste	s - e -CO2 ods: 9 of ck, CO3 ods: 9 C), CO4 ods: 9 led ind em, CO5 ind

- 1. LPC 214x User manual (UM10139): www.nxp.com
- 2. LPC 17xx User manual (UM10360): www.nxp.com
- 3. ARM architecture reference manual: www.arm.com
- $4.\ http://processors.wiki.ti.com/index.php/HandsOn_Training_for_TI_Embedded_Processors$
- 5. http://processors.wiki.ti.com/index.php/MCU_Day_Internet_of_Things_2013_Workshop

COs/POs/PSOs Mapping

COs		Prog	ram Out	comes (POs)		Program S	Specific Outcom	es (PSOs)
COS	PO1	PO2	PO3	PO4	PO5	PO6	PSO1	PSO2	PSO3
1	3	3	3	3	3	-	3	2	-
2	3	3	3	3	3	-	3	2	-
3	3	3	3	3	3	-	3	2	-
4	3	3	3	3	3	-	3	2	-
5	3	3	3	3	3	-	3	2	-

Correlation Level: 1 - Low, 2 - Medium, 3 – High

Evaluation Method

	Contir	nuous Asse	ssment Marks (CAM)	End Semester	Total
CAT	CAT	Model	Assignment*	Attendance	Examination (ESE)	Marks
	2	Exam			Ivial KS	
10		15	10	5	60	100
	1	CAT CAT 1 2	CATCATModel12Exam	CATCATModel12Exam	1 2 Exam Assignment* Attendance	CAT 1CAT 2Model ExamAssignment*AttendanceExamination (ESE)

		ECE			v	Programme: M.Tech EC Course Category Code: *End Sem							
Semester		I		PE				Ту	nester E /pe: TE				
Course		P23ECE101	Pe	riods/W	/eek	C	redit	Max	kimum N	larks			
Code		FZJEGEIVI	L	Т	Р	()	CAM	ESE	ТМ			
Course	Adv	vanced Microprocessor	3	0	0		3	40	60	100			
Name		and Interfacing											
Prerequisite													
•													
		On completion of the cou				able	e to		BT Ma (Highes	apping st Leve			
		CO1 Explain advanced microprocessor architecture											
Course	CO2	Interpret modular programm	ing conce	pts					K	(2			
Outcome	CO3	Describe organization PIC16	6F877 mio	crocontro	ollers				K	(2			
	CO4	Interface peripheral devices	with PIC	6F877 I	Microcon	trolle	ers		k	(3			
	CO5	Design and develop on Micr	ocontrolle	r Based	system	desi	an		k	(4			
							9		•				
Unit - I	Adva	anced Microprocessor Arch	itecture						Ре	riods:			
Internal Micro	oproce	ssor Architecture-Real mode	memory a	addressii	ng – Pro	tecte	d Mo	ode Mer	nory				
-		ry paging - Data addressing m		-	-			-		CO1			
		essing modes – Data movem	nent instru	ctions –	Program	n cor	ntrol i	nstructio	ons-	001			
	_	c Instructions											
Unit - II	<u>i</u>	ular Programming and its C	-			•		-	<u>l</u>	riods:			
	•	h-level synthesis, Logic synth	esis Loa	o optimi		Nd +0	chno		nning				
	1	· · · · · · · · · · · · · · · · · · ·		•				0,	apping,	CO2			
-	·····	ology mapping, Timing analys		•				0,					
Unit - III	PIC I	Microcontroller	sis, Timing	optimiz	ation, Ar	ea o	ptim	ization	Pe				
Unit - III Architecture	PIC I – mem	Microcontroller ory organization – addressing	sis, Timing g modes -	optimiz - instruct	ation, Ar ion set –	ea o - PIC	ptim	ization grammir	Pe	riods:			
Unit - III Architecture Assembly &	PIC I – mem C –I/O	Microcontroller ory organization – addressing port, Data Conversion, RAM	sis, Timing g modes - & ROM A	optimiz - instruct	ation, Ar ion set –	ea o - PIC	ptim	ization grammir	Pe ng in	cO3			
Unit - III Architecture Assembly & Unit - IV	PIC I – mem C –I/O Perip	Microcontroller ory organization – addressing port, Data Conversion, RAM oheral of Pic Microcontrolle	sis, Timing g modes - & ROM A r	optimiz - instruct llocation	ation, Ar ion set – , Timer p	ea o - PIC progi	ptim prog amn	ization grammir ning	Pe ng in Pe	CO3 riods:			
Unit - III Architecture Assembly & Unit - IV Timers – Inte	PIC I – mem C –I/O Periț errupts,	Microcontroller ory organization – addressing port, Data Conversion, RAM	sis, Timing g modes - & ROM A r	optimiz - instruct llocation	ation, Ar ion set – , Timer p	ea o - PIC progi	ptim prog amn	ization grammir ning	Pe ng in Pe	cO3			
Unit - III Architecture Assembly & Unit - IV Timers – Inte	PIC I – mem C –I/O Perip errupts, Flash a	Microcontroller ory organization – addressing port, Data Conversion, RAM oheral of Pic Microcontroller I/O ports- I2C bus-A/D conve	sis, Timing g modes - & ROM A r	optimiz - instruct llocation	ation, Ar ion set – , Timer p	ea o - PIC progi	ptim prog amn	ization grammir ning	Pe ng in Pe Sensor	cO3 CO3 cO4			
Unit - III Architecture Assembly & Unit - IV Timers – Inte Interfacing – Unit - V	PIC I – mem C –I/O Perip errupts, Flash a Instr	Microcontroller ory organization – addressing port, Data Conversion, RAM oheral of Pic Microcontroller I/O ports- I2C bus-A/D conve and EEPROM memories.	sis, Timing g modes - & ROM A r erter-UAR	optimiz - instruct Ilocation T- CCP	ation, Ar ion set – , Timer p modules	- PIC progi	ptim prog amm C, D	grammir hing AC and	Peoperation Peoper	cO3 cO3 cO4			
Unit - III Architecture Assembly & Unit - IV Timers – Inter Interfacing –I Unit - V Microcontroll Gate signals	PIC I – mem C –I/O Perip errupts, Flash a Instr ler base for cor	Microcontroller ory organization – addressing port, Data Conversion, RAM oheral of Pic Microcontroller I/O ports- I2C bus-A/D conver and EEPROM memories. uctional Activity ed system design: Interfacing overters and Inverters - Motor	sis, Timing g modes – & ROM A r erter-UAR LCD Disp Control –	9 optimiz - instruct Ilocation T- CCP Dlay – Ke - Control	ation, Ar ion set – , Timer p modules eypad Int ling DC/	- PIC progr - AD	ptim prog amn C, D cing	grammir hing AC and - Gener	Pe ng in Sensor Pe ation of	riods: CO3 riods: CO4 riods:			
Unit - III Architecture Assembly & Unit - IV Timers – Inter Interfacing – Unit - V Microcontroll Gate signals Measuremen	PIC I – mem C –I/O Perip errupts, Flash a Instr ler base for cor nt of fre	Microcontroller ory organization – addressing port, Data Conversion, RAM oheral of Pic Microcontroller I/O ports- I2C bus-A/D convert and EEPROM memories. uctional Activity ed system design: Interfacing overters and Inverters - Motor equency – Standalone Data Addressing	sis, Timing g modes - & ROM A r erter-UAR LCD Disp Control - cquisition	- instruct llocation T- CCP blay – Ke Control System.	ation, Ar ion set – , Timer p modules eypad Int ling DC/	ea o PIC progi - AD terfa	ptim prog amn C, D cing	grammir hing AC and - Gener ances –	Pe ng in Sensor Pe ation of	riods: CO3 riods: CO4 riods: CO5			
Unit - III Architecture Assembly & Unit - IV Timers – Inte Interfacing –I Unit - V Microcontroll Gate signals Measuremen Lecture Pe	PIC I – mem C –I/O Perip errupts, Flash a Instr ler base for cor nt of fre	Microcontroller ory organization – addressing port, Data Conversion, RAM oheral of Pic Microcontroller I/O ports- I2C bus-A/D convert and EEPROM memories. uctional Activity ed system design: Interfacing overters and Inverters - Motor equency – Standalone Data Addressing	sis, Timing g modes - & ROM A r erter-UAR LCD Disp Control - cquisition	- instruct llocation T- CCP blay – Ke Control System.	ation, Ar ion set – , Timer p modules eypad Int ling DC/	ea o PIC progi - AD terfa	ptim prog amn C, D cing	grammir hing AC and - Gener ances –	Pe ng in Sensor Pe ation of	cO3 cO4 cO4 cO4 cO5			
Unit - III Architecture Assembly & Unit - IV Timers – Inte Interfacing – Unit - V Microcontroll Gate signals Measuremen Lecture Pe extbooks	PIC I – mem C –I/O Perip errupts, Flash a Instr ler base for cor- nt of fre- eriods:	Microcontroller ory organization – addressing port, Data Conversion, RAM oheral of Pic Microcontroller I/O ports- I2C bus-A/D convert and EEPROM memories. uctional Activity ed system design: Interfacing overters and Inverters - Motor equency – Standalone Data Activity at a converter of the system design: Interfacing overters and Inverters - Motor	sis, Timing g modes – & ROM A r erter-UAR LCD Disp Control – cquisition Pr	- instruct llocation T- CCP blay – Ke - Control System.	ation, Ar ion set – , Timer p modules eypad Int ling DC/ Periods :	ea c - PIC progr - AD terfa AC :	ptim ; prog amm C, D cing appli	ration grammir hing AC and - Gener ances – Tota	Peng in Peng in Sensor Penation of	riods: CO3 riods: CO4 riods: CO5 s: 45			
Unit - III Architecture Assembly & Unit - IV Timers – Inte Interfacing – Unit - V Microcontroll Gate signals Measuremen Lecture Per extbooks 1. Danny (PIC I – mem C –I/O Perip errupts, Flash a Instr ler base for cor ht of fre eriods: Causey	Microcontroller ory organization – addressing port, Data Conversion, RAM oheral of Pic Microcontroller I/O ports- I2C bus-A/D converted and EEPROM memories. uctional Activity ed system design: Interfacing overters and Inverters - Motor oquency – Standalone Data Activity etage 45 Tutorial Periods: - v, Rolin McKinlay and Muh	sis, Timing g modes – & ROM A r erter-UAR LCD Disp Control – cquisition Pr	- instruct llocation T- CCP blay – Ke - Control System. actical l	ation, Ar ion set – , Timer p modules eypad Int ling DC/ Periods : idi 'PIC	ea c - PIC progr - AD terfa AC :	ptim ; prog amm C, D cing appli	ration grammir hing AC and - Gener ances – Tota	Peng in Peng in Sensor Penation of	riods: CO3 riods: CO4 riods: CO5 s: 45			
Unit - III Architecture Assembly & Unit - IV Timers – Inte Interfacing – Unit - V Microcontroll Gate signals Measuremen Lecture Pe extbooks 1. Danny (Systems 2. Daniele	PIC I – mem C –I/O Perip errupts, Flash a Instr ler base for cor t of fre eriods: Causey: Using Lacam	Microcontroller ory organization – addressing port, Data Conversion, RAM oheral of Pic Microcontroller I/O ports- I2C bus-A/D conver- and EEPROM memories. uctional Activity ed system design: Interfacing overters and Inverters - Motor quency – Standalone Data Activity at 5 Tutorial Periods: - r, Rolin McKinlay and Muh g Assembly and C for PIC18', era, 'Embedded Systems Arc	sis, Timing g modes - & ROM A r erter-UAR LCD Disp Control - cquisition Pr nammad Microdigit chitecture:	- instruct llocation T- CCP Dlay – Ke Control System. actical Ali Maz taled, 20 Explore	ation, Ar ion set – , Timer p modules eypad Int ling DC/ Periods: idi 'PIC 16 e archite	ea c PIC orogi - AD terfa AC : - Mic	ptim prog ramn C, D cing appli croco	aration grammir hing AC and - Gener ances – Tota ntroller	Pe ng in Sensor Pe ation of I Periods and Er pragmati	riods: CO3 riods: CO4 riods: CO5 s: 45			
Unit - III Architecture Assembly & Unit - IV Timers – Inte Interfacing – Unit - V Microcontroll Gate signals Measuremen Lecture Pe extbooks 1. Danny (Systems 2. Daniele patterns,	PIC I – mem C –I/O Perip errupts, Flash a Instr ler base for cor t of fre eriods: Causey: Using Lacam , and be	Microcontroller ory organization – addressing port, Data Conversion, RAM oheral of Pic Microcontroller I/O ports- I2C bus-A/D conver- and EEPROM memories. uctional Activity ed system design: Interfacing overters and Inverters - Motor quency – Standalone Data Activity at Tutorial Periods: - r, Rolin McKinlay and Muh a Assembly and C for PIC18', era, 'Embedded Systems Arc est practices to produce robus	sis, Timing g modes - & ROM A r erter-UAR LCD Disp Control - cquisition Pr nammad Microdigi chitecture: st system	- instruct llocation T- CCP Dlay – Ke Control System. actical Ali Maz taled, 20 Explore s', Packt	ation, Ar ion set – , Timer p modules eypad Inf ling DC/ Periods: idi 'PIC 16 e archited Publishi	ea c PIC orogi - AD terfa AC : - Mic ctura	ptim prog amn C, D cing appli croco	AC and - Gener ances – Tota ntroller acepts,	Pe ng in Sensor Pe ation of I Periods and Er	riods: CO3 riods: CO4 riods: CO5 s: 45 nbedde c desig			
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- 2. http:// www.microchip.com/design-centers/microcontrollers
- 3. https://learn.mikroe.com/
- 4. https://microcontrollerslab.com/pic-microcontroller-architecture/
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- * TE Theory Exam, LE Lab Exam

COs/POs/PSOs Mapping

		Prog		comes	(POs)		Program Specific Outcomes (PSOs)				
COs	PO1	PO2	PO3	PO4	PO5	PO6	PSO1	PSO2	PSO3		
1	2	-	3	3	-	1	3	-	3		
2	2	-	3	3	-	1	3	-	3		
3	2	-	3	3	-	1	3	-	3		
4	2	-	3	3	-	1	3	-	3		
5	2	2	3	3	2	1	3	-	3		

Correlation Level: 1 - Low, 2 - Medium, 3 – High

Evaluation Method

		Contir	nuous Asse	ssment Marks (CAM)	End Semester	Total
Assessment	CAT	CAT	Model	Assignment*	Attendance	Examination (ESE)	Marks
	1	2	Exam	Assignment	Allenuance	Marks	iviai ko
Marks	10		15	10	5	60	100

Department		ECE		<u>w</u>	me: M.T					
Semester		II	Co	urse Ca PE		: *E	nd Sen Ty	nester E pe: TE	Exam	
Course		P23VEEC02		iods/W	1	Credit		imum M	T	
Code			L	Т	P	C	CAM	ESE	TM	
Course Name	I.	nternet of Things and its Implementation	3	40	60	100				
Prerequisite	Nil									
		On completion of the course, the students will be able to (Highe Level								
Course	CO1 Articulate the main concepts, key technologies, strength and limitations of IoT								K2	
Outcome	CO2	Identify the architecture, infrast	ructure r	nodels c	of IoT				K2	
	CO3	Analyze the networking and ho	w the se	nsors ar	re comn	nunicated	l in IoT.		K3	
	CO4	Analyze and design different m	odels foi	· IoT imp	olement	ation.			K3	
	CO5	, , ,							K3	
Init - I	Intro	duction to Internet of Things (Peri	ods: 9	
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- 5. https://www.codeproject.com/Learn/IoT/

* TE – Theory Exam, LE – Lab Exam

COs/POs/PSOs Mapping

COs	Program Outcomes (POs) Program Specific ((PSOs)						-	itcomes	
	PO1	PO2	PO3	PO4	PO5	PO6	PSO1	PSO2	PSO3
1	2	-	3	3	-	1	3	-	3
2	2	-	3	3	-	1	3	-	3
3	2	-	3	3	-	1	3	-	3
4	2	-	3	3	-	1	3	-	3
5	2	2	3	3	2	1	3	-	3

Correlation Level: 1 - Low, 2 - Medium, 3 – High

Evaluation Method

		Contir	nuous Asse	ssment Marks (CAM)	End Semester	Total
Assessment	CAT	CAT	Model	Assignment*	Attendance	Examination (ESE)	Marks
	1	2	Exam	Assignment	Attenuance	Marks	Walks
Marks	1	10 15		10	5	60	100

ANNEXURE – 2 (A): CURRICULUM

M.Tech - VLSI and Embedded Systems



Puducherry

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

M.TECH.

VLSI AND EMBEDDED SYSTEMS

(REGULATIONS-2023)

CURRICULUM & SYLLABI



VISION AND MISSION OF THE INSTITUTE

VISION

To be globally recognized for excellence in quality education, innovation and research for the transformation of lives to serve the society.

MISSION

M1: Quality Education	To provide comprehensive academic system that amalgamates the cutting edge-technologies with best practices
M2: Research and Innovation	To foster value-based research and innovation in collaboration with industries and institutions globally for creating intellectuals with new avenues
M3: Employability and Entrepreneurship	To inculcate the employability and entrepreneurial skills through value and skill-based training
M4: Ethical Values	To instil deep sense of human values by blending societal righteousness with academic professionalism for the growth of society

VISION AND MISSION OF THE DEPARTMENT

VISION

Facilitate academic excellence and research among Electronics and Communication Engineers to meet the Global needs with high competence and ethical professionalism

MISSION

M1: Academic Excellence	To impart learning skills to meet the global challenges in the field of Electronics and Communication Engineering							
M2: Research and Innovation	To provide excellence in research and innovation through multidisciplinary specialization							
M3: Employability and Entrepreneurship	To enhance inter and intrapersonal skills among students to make them employable and entrepreneurs							
M4: Ethics	To inculcate the significance of human values and professional skills to serve the society							

PROGRAMME OUTCOMES (POs)

PO1: Exploration of Research:

An ability to independently carry out research/investigation and development work to solve practical problems.

PO2: Technical Skill:

An ability to write and present a substantial technical report/document.

PO3: Expertise in Academics:

Students should be able to demonstrate a degree of mastery over the area as per the specialization of the program. The mastery should be at a level higher than the requirements in the appropriate bachelor program.

PO4: Scholarship of Knowledge:

Acquire in-depth knowledge of specific discipline or professional area, including wider and global perspective, with an ability to discriminate, evaluate, analyze and synthesize existing and new knowledge, and integration of the same for enhancement of knowledge.

PO5: Usage of Modern Tools:

Create, select, learn and apply appropriate techniques, resources, and modern engineering and IT tools, including prediction and modelling, to complex engineering activities with an understanding of the limitations.

PO6: Ethical Practices and Social Responsibility:

Acquire professional and intellectual integrity, professional code of conduct, ethics of research and scholarship, consideration of the impact of research outcomes on professional practices and an understanding of responsibility to contribute to the community for sustainable development of society.

PROGRAM EDUCATIONAL OBJECTIVES (PEOs)

PEO1: Technical Knowledge

Graduates will be able to develop an insightful combination of modern electronics and communication technology through technical knowledge.

PEO2: Research and Development

Enhance analytical and thinking skills to develop initiatives and innovative ideas for research and development, industry and societal requirements.

PEO3: Leadership

Inculcate the qualities of teamwork as well as social, interpersonal and leadership skills and adapt to the changing professional environments in the fields of engineering and technology

PEO4: Professional Ethics

Motivate graduates to become good human beings and responsible citizens for the overall welfare of the society.

PROGRAM SPECIFIC OUTCOMES (PSOs)

PSO1: Domain Knowledge

Ability to understand the concepts in Electronics and Communication Engineering and to apply to different fields, such as Consumer Electronics, Communications, Signal Processing, etc.

PSO2: Embedded System Design

Ability to design a system based on the technical knowledge gained for embedded applications in electronics and communications engineering.

PSO3: Professional Competency

Ability to select cutting-edge engineering hardware and software tools to solve complex problems in Electronics and Communication Engineering

SEMESTER-I

SI.	Course Code	ourse Code Course Title Category	Periods		ds	Cradita	Max. Marks				
No.	Course Code	Course Title	Category	L	Т	Ρ	Credits	CAM	ESM	Total	
Theo	Theory										
1	P23MAT102	Applied Mathematics for VLSI	BS	2	2	0	3	40	60	100	
2	P23VET101	Electronic Design Automation Tools	PC	3	0	0	3	40	60	100	
3	P23VET102	FPGA Based System Design	PC	3	0	0	3	40	60	100	
4	P23VET103	VLSI Design Techniques	PC	3	0	0	3	40	60	100	
5	P23HSTC01	Research Methodology and IPR	HS	2	0	0	2	40	60	100	
6	P23VEE1XX	Professional Elective - I	PE	3	0	0	3	40	60	100	
Prac	tical										
7	P23VEP101	VLSI Design Laboratory	PC	0	0	4	2	50	50	100	
8	P23HSTC02	Technical Report Writing and Seminar	HS	0	0	4	2	100	0	100	
Abili	Ability Enhancement Course										
9	P23VEC1XX	Certification Course – I	AEC	0	0	4	-	100	-	100	
10	P23ACT10X	Audit Course - I	AEC	2	0	0	-	100	•	100	
							21	590	410	1000	

SEMESTER-II

SI.	Course Code	Course Title	Cotogony	Pe	erio	ds	Credits	Max. Marks		
No.	Course Code	Course The	Category	Ъ	Т	Ρ	Credits	CAM	ESM	Total
Theory										
1	P23VETC01	Advanced Digital System Design	PC	3	0	0	3	40	60	100
2	P23VETC02	Embedded Processors	PC	3	0	0	3	40	60	100
3	P23VETC03	Embedded System Design	PC	3	0	0	3	40	60	100
4	P23VET204	Low Power Digital VLSI Design	PC	3	0	0	3	40	60	100
5	P23VEE2XX	Professional Elective - II	PE	3	0	0	3	40	60	100
6	P23VEE2XX	Professional Elective - III	PE	3	0	0	3	40	60	100
		Pract	ical							
7	P23VEP202	Embedded System Design Laboratory	PC	0	0	4	2	50	50	100
8	P23HSTC03	Seminar on ICT a hands-on approach	HS	0	0	4	2	100	0	100
		Ability Enhance	ement Cou	rse						
10	P23VEC2XX	Certification Course – II	AEC	0	0	4	-	100	-	100
11	P23ACT20X	Audit Course - II	AEC	2	0	0	-	100	-	100
Total						22	590	410	1000	

SEMESTER-III

SI. No. Course Co	Course Code	Course Code Course Title Category	ds	Cradita	Max. Marks					
	Course Code		Category	L	Т	Ρ	Credits	CAM	ESM	Total
	· · · ·	The	ory							
1	P23VEE3XX	Professional Elective - IV	PE	3	0	0	3	40	60	100
2	P23VEE3XX	Professional Elective - V	PE	3	0	0	3	40	60	100
3	P23VEE3XX	Professional Elective - VI	PE	3	0	0	3	40	60	100
		Project	Work							
7	P23VEW301	Project Phase - I	PA	0	0	12	6	50	50	100
8	P23VEW302	Internship	PA	0	0	0	2	100	0	100
Ability Enhancement Course										
10	P23VEC301	NPTEL / SWAYAM / MOOC	AEC	0	0	0	-	100	0	100
Total					17	370	230	600		

SEMESTER-IV

SI. Course Code			Cotogony	Periods	Credits	М	ax. Mar	ks		
No.	Course Code Course Title Category		L	Т	Р	Credits	CAM	ESM	Total	
Project Work										
1	P23VEW303	Project Phase - II	PA	0	0	24	12	50	50	100
	Total					12	50	50	100	

* Professional Elective Courses are to be selected from the list given in Annexure I

Ability Enhancement Courses are to be selected from the list given in Annexure II

** Audit Courses are to be selected from the list given in Annexure III

- BS Basic Science
- HS Humanity Science
- PC Professional Core
- PE Professional Elective
- PA Project Work
- C Common Course

AEC – Audit Course

AEC – Ability Enhancement Course

Credit Distribution

Semester- I	Semester - II	Semester - III	Semester - IV	Total
21	22	17	12	72

Total number of credits required to complete	70
M. Tech - VLSI AND Embedded Systems:	72 credits

Annexure – A

PROFESSIONAL ELECTIVE COURSES

Profes	sional Elective	–I (Offered in Semester I)
SI. No.	Course Code	Course Title
1	P23VEE101	Principles of ASIC Design
2	P23VEE102	VLSI Architecture
3	P23VEE103	Physical Design of VLSI
4	P23VEE104	Real Time Systems
5	P23VEE105	Analog IC Design
Profes		– II (Offered in Semester II)
SI. No	Course Code	Course Title
1	P23VEEC01	Design of Analog and Mixed VLSI Circuits
2	P23VEEC02	Internet of Things and its Implementation
3	P23VEE206	Modeling and Synthesis with Verilog HDL
4	P23VEE207	Advanced Embedded System
5	P23VEE208	Distributed Embedded Computing
		-III (Offered in Semester II)
SI. No	Course Code	Course Title
1	P23VEEC03	System-on-Chip Design
2	P23VEE309	DSP Processor Architecture and Programming
3	P23VEE310	Design for Verification Using UVM
4	P23VEE311	Testing and Fault Diagnosis of VLSI Circuits
5	P23VEE312	Soft Computing
Profes	sional Elective-	-IV (Offered in Semester III)
SI. No	Course Code	Course Title
1	P23VEEC04	Real Time Operating System
2	P23VEEC05	Cloud computing and Distributed System
3	P23VEE313	VLSI Signal Processing
4	P23VEE414	High Speed Digital Design
5	P23VEE415	Computer Design Automation for VLSI Circuits
		-V (Offered in Semester III)
SI. No	Course Code	Course Title
1	P23VEEC06	Edge Computing
2	P23VEE416	CAD for VLSI Circuits
3	P23VEE217	Advanced Image Processing
4	P23VEE218	Hardware Software Co-Design
5	P23VEE519	Micro-Electromechanical Systems
Profes	sional Elective-	-VI (Offered in Semester III)
SI. No	Course Code	Course Title
1	P23VEE520	Pervasive Devices and Technology
2	P23VEE521	Robotics and Automation
3	P23VEE622	Semiconductor Devices and Modeling
4	P23VEE623	VLSI for Wireless Communication
5	P23VEE624	RISC Processor Architecture and Programming

S. No	Course Code	ABILITY ENHANCEMENT COURSES Course Title	Certified By
1	P23XXCX01		Adobe
		Adobe Photoshop	
2	P23XXCX02	Adobe Animate	Adobe Adobe
3	P23XXCX03	Adobe Dreamweaver	
4	P23XXCX04	Adobe After Effects	Adobe
5	P23XXCX05	Adobe Illustrator	Adobe
6	P23XXCX06	Adobe InDesign	Adobe
7	P23XXCX07	Autodesk AutoCAD -ACU	Autodesk
8	P23XXCX08	Autodesk Inventor - ACU	Autodesk
9	P23XXCX09	Autodesk Revit - ACU	Autodesk
10	P23XXCX10	Autodesk Fusion 360 - ACU	Autodesk
11	P23XXCX11	Autodesk 3ds Max - ACU	Autodesk
12	P23XXCX12	Autodesk Maya - ACU	Autodesk
13	P23XXCX13	Cloud Security Foundations	AWS
14	P23XXCX14	Cloud Computing Architecture	AWS
15	P23XXCX15	Cloud Foundation	AWS
16	P23XXCX16	Cloud Practitioner	AWS
17	P23XXCX17	Cloud Solution Architect	AWS
18	P23XXCX18	Data Engineering	AWS
19	P23XXCX19	Machine Learning Foundation	AWS
20	P23XXCX20	Robotic Process Automation / Medical Robotics	Blue Prism
21	P23XXCX21	Advance Programming Using C	CISCO
22	P23XXCX22	Advance Programming Using C ++	CISCO
23	P23XXCX23	C Programming	CISCO
24	P23XXCX24	C++ Programming	CISCO
25	P23XXCX25	CCNP Enterprise: Advanced Routing	CISCO
26	P23XXCX26	CCNP Enterprise: Core Networking	CISCO
27	P23XXCX27	Cisco Certified Network Associate - Level 2	CISCO
28	P23XXCX28	Cisco Certified Network Associate- Level 1	CISCO
29	P23XXCX29	Cisco Certified Network Associate- Level 3	CISCO
30	P23XXCX30	Fundamentals of Internet of Things	CISCO
31	P23XXCX31	Internet of Things / Solar and Smart Energy System with IoT	CISCO
32	P23XXCX32	Java Script Programming	CISCO
33	P23XXCX33	NGD Linux Essentials	CISCO
34	P23XXCX34	NGD Linux I	CISCO
35	P23XXCX35	NGD Linux II	CISCO
36	P23XXCX36	Advance Java Programming	Ethnotech
37	P23XXCX37	Android Programming / Android Medical App Development	Ethnotech
38	P23XXCX38	Angular JS	Ethnotech
39	P23XXCX39	Catia	Ethnotech
40	P23XXCX40	Communication Skills for Business	Ethnotech
41	P23XXCX41	Coral Draw	Ethnotech
42	P23XXCX42	Data Science Using R	Ethnotech
43	P23XXCX43	Digital Marketing	Ethnotech
44	P23XXCX44	Embedded System Using C	Ethnotech
45	P23XXCX45	Embedded System with IoT / Arduino	Ethnotech
46	P23XXCX46	English for IT	Ethnotech
10	1 20///0//40		

Annexure – B ABILITY ENHANCEMENT COURSES

S. No	Course Code	Course Title	Certified By
47	P23XXCX47	Plaxis	Ethnotech
48	P23XXCX48	Sketch Up	Ethnotech
49	P23XXCX49	Financial Planning, Banking and Investment Management	Ethnotech
50	P23XXCX50	Foundation of Stock Market Investing	Ethnotech
51	P23XXCX51	Machine Learning / Machine Learning for Medical Diagnosis	Ethnotech
52	P23XXCX52	IOT Using Python	Ethnotech
53	P23XXCX53	Creo (Modelling & Simulation)	Ethnotech
54	P23XXCX54	Soft Skills, Verbal, Aptitude	Ethnotech
55	P23XXCX55	Software Testing	Ethnotech
56	P23XXCX56	MX-Road	Ethnotech
57	P23XXCX57	CLO 3D	Ethnotech
58	P23XXCX58	Solid works	Ethnotech
59	P23XXCX59	Staad Pro	Ethnotech
60	P23XXCX60	Total Station	Ethnotech
61	P23XXCX61	Hydraulic Automation	Festo
62	P23XXCX62	Industrial Automation	Festo
63	P23XXCX63	Pneumatics Automation	Festo
64	P23XXCX64	Agile Methodologies	IBM
65	P23XXCX65	Block Chain	IBM
66	P23XXCX66	Devops	IBM
67	P23XXCX67	Artificial Intelligence	ITS
68	P23XXCX68	Cloud Computing	ITS
69	P23XXCX69	Computational Thinking	ITS
70	P23XXCX70	Cyber Security	ITS
71	P23XXCX71	Data Analytics	ITS
72	P23XXCX72	Databases	ITS
73	P23XXCX73	Java Programming	ITS
74	P23XXCX74	Networking	ITS
75	P23XXCX75	Python Programming	ITS
76	P23XXCX76	Web Application Development (HTML, CSS, JS)	ITS
			ITS & Palo
77	P23XXCX77	Network Security	alto
78	P23XXCX78	MATLAB	MathWorks
79	P23XXCX79	Azure Fundamentals	Microsoft
80	P23XXCX80	Azure AI (AI-900)	Microsoft
81	P23XXCX81	Azure Data (DP -900)	Microsoft
82	P23XXCX82	Microsoft 365 Fundamentals (SS-900)	Microsoft
83	P23XXCX83	Microsoft Security, Compliance and Identity (SC-900)	Microsoft
84	P23XXCX84	Microsoft Power Platform (PI-900)	Microsoft
85	P23XXCX85	Microsoft Dynamics Fundamentals 365 – CRM	Microsoft
86	P23XXCX86	Microsoft Excel	Microsoft
87	P23XXCX87	Microsoft Excel Expert	Microsoft
88	P23XXCX88	Securities Market Foundation	NISM
89	P23XXCX89	Derivatives Equinity	NISM
90	P23XXCX90	Research Analyst	NISM
91	P23XXCX91	Portfolio Management Services	NISM
92	P23XXCX92	Cyber Security	Palo alto

S. No	Course Code	Course Title	Certified By
93	P23XXCX93	Cloud Security	Palo alto
94	P23XXCX94	PMI – Ready	PMI
95	P23XXCX95	Tally – GST & TDS	Tally
96	P23XXCX96	Advance Tally	Tally
97	P23XXCX97	Associate Artist	Unity
98	P23XXCX98	Certified Unity Programming	Unity
99	P23XXCX99	VR Development	Unity

*Any one course to be selected from the list

Annexure - C

AUDIT COURSES

SI. No.	Course Code	Course Title
1	P23ACTX01	English for Research Paper Writing
2	P23ACTX02	Disaster Management
3	P23ACTX03	Sanskrit for Technical Knowledge
4	P23ACTX04	Value Education
5	P23ACTX05	Constitution of India
6	P23ACTX06	Pedagogy Studies
7	P23ACTX07	Stress Management by Yoga
8	P23ACTX08	Personality Development Through Life Enlightenment Skills
9	P23ACTX09	Unnat Bharat Abhiyan

ANNEXURES - 2 (B) UPDATED SYLLABUS

M.Tech - VLSI and Embedded Systems

Professional Core Course

Semester	Course Code	Course Title
I	P23VET101	Electronic Design Automation Tools
II	P23VETC02	Embedded Processors

Elective Course

Semester	Course Code	Course Title					
I	P23VEE105	Analog IC Design					
II	P23VEE310	Design for Verification Using UVM					
II	P23VEE311	Testing and Fault Diagnosis of VLSI Circuits					

Department		ECE	Progra	mme: M.	Tech	VLSI & E	ES			
Semester		I Course Category: PC *End Semester Exar								
Course Code	<u>د</u>	P23VET101	Pe	riods/We	eek	Credit	Max	ximum Mar ESE 60 BT Map (Highest I 3 3 3 3 4 Periods: els, Delay istor-Level Periods: Synthesis, Periods: al System Periods: al System Periods: al System Periods: A Periods: A	rks	
			L	T	Р	С	CAM		ТМ	
Course Name	Ele	ctronic Design Automation Tools	3	0	0	3	40	60	100	
Prerequisite	VER	LOG, VHDL						7		
		mpletion of the course, the s								
	CO1	Understand Functional desig	n and ve	rification	models	i.		3		
Course	CO2	Synthesize circuits using HD	L codes.					3		
Outcome	CO3	Design circuits, IC design flow	w using l	PSPICE	tool,			3		
	CO4	Design Mixed signal design f	low for ir	ntegrated	circuit	design.		3		
	CO5	Implement Microelectronics of (EDA) tools.	design us	sing Elec	tronic D	esign Aut	omation	4		
Unit-I		Ilation Using HDL						<u>i</u>	: 9	
		of Simulation, Logic Systems, ning Analysis, Formal Verifi							CO1	
Unit-II	Synt	hesis Using HDL						Periods	: 9	
Memory Sy	nthesis,	Synthesis, VHDL and Logic Performance-Driven Synthesi ulation and Synthesis: Modelsi	is.		-	-	FSM S	Synthesis,	CO2	
Unit-III		uit Design and Simulation Us						Periods	: 9	
		Transistors, A/D & D/A Sar sign and Analysis of Analog a	•				d Digita	I System	СОЗ	
Unit-IV		overview of Mixed Signal VL						<u>.</u>	: 9	
		Analog and Digital Simu leling, Integration to CAD Envi			Signal	Simulator	· Config	gurations,	CO4	
Unit-V		uctional Activity						<u>.</u>	: 9	
An Overvie Introduction	w of H to OrC	igh-Speed PCB Design, Des AD PCB Design Tools.	ign Entr	y, Simul	ation a	nd Layou	t Tools	for PCB,	CO5	
Lecture P	Periods:	45 Tutorial Periods: -	F	ractical l	Periods	-	Tota	I Periods:	45	
Fextbooks										
2. J.Bha	askar, "A RASHID	A Verilog Primer", BSP, 2003. A Verilog HDL Synthesis", BSF 9, "SPICE FOR Circuits and		nicsUsing	PSPIC	E", (2/E)	(1992) P	rentice Ha		
	S.SMITH	I, "Application-Specific Integra			97). Ad	dison We	sley.			
		A VHDL Synthesis Primer", BS								
2. J.Bha Neb Referen	ces									
2. J.Bha Veb Referen 1. https:	i ces //nptel.a	ac.in/courses/106105083	sn50/nr	eview						
2. J.Bha Neb Referen 1. https: 2. https: 3. https:	i ces //nptel.a //online	ac.in/courses/106105083 courses.swayam2.ac.in/aic20_ otechguru.com/coursesnptel-			gn-auto	mation-vi	deo-lecti	urecse		

COs/POs/PSOs Mapping

	Program Outcomes (POs)						Program Specific Outcomes (PSOs)		
COs	PO1	PO2	PO3	PO4	PO5	PO6	PSO1	PSO2	PSO3
1	2	2	1	2	-	1	3	2	-
2	2	2	1	2	-	1	3	2	-
3	2	2	1	2	-	1	3	2	-
4	2	2	1	2	-	1	3	2	-
5	2	2	1	2	2	1	3	2	-

Correlation Level: 1 - Low, 2 - Medium, 3 - High

Evaluation Method

		Contir	nuous Asse	ssment Marks (End Semester	Total		
Assessment	CAT CAT		Model	Assignment*	Attendance	Examination (ESE)	Marks	
	1	2	Exam	Assignment	Attenuance	Marks	IVIAI NO	
Marks	10		15	10	5	60	100	

Department	ECE	Programme: M.Tech. VLSI & ES							
Semester	II	Course (Category	PC	*End S	emester	Exam Type: TE		
		Periods/	Week		Credit	Maxim	um Mark	S	
Course Code	P23VETC02	L	Т	Р	С	CAM	ESE	ТМ	
Course Name	Embedded Processors	3	0	0	3	40	60	100	
	(Common to M.Tec	ch ECE and	d M.Tech	– VLSI	& ES)	<u>-</u>	<u>.</u>	<u>.</u>	
Prerequisite	Microcontroller								
	On completion of the course,	the stude	nts will l	be able	to		BT Ma (Highes	apping st Level	
	CO1 Analyze the architectures	s of differe	nt Embec	Ided Pro	ocessors			3	
Course Outcome	CO2 Identify an appropriate or communication					allel	2	2	
Outcomo	CO3 Examine the functions of	ARM proc	essors				;	3	
	CO4 Develop real time applica	ations usin	a ARM p	rocesso	rs			3	
	CO4Develop real time applications using ARM processorsCO5Develop a firmware for embedded applications								
							<u>-</u>		
Unit-I	Introduction to Embedded F	Processor	S				Period	ls: 9	
Buses Unit-II Vemory - Interr	Embedded Processors on Ch			Watch	dog time	ar - CCP	Periods		
Memory - Interr	upts - I/O Ports-Timers & Real Compare Mode-PWM Mode - S	Time Cloc	k (RTC),				modules	-	
2C interface, A	nalog Comparator, Analog interfa	acing and	data acqu	uisition.					
Unit-III	ARM Processor						Period	,	
operation - D/A	ARM Controller – Registers, Pip and A/D converter, sensors, act nsing, Light sensing, Introductio	uators and	their inte	erfacing	- Case	study- Di	gital cloc		
Unit-IV	Real World Interfacing Using	g ARM Pro	ocessor				Period	ls: 9	
	peripherals to LPC2148: GSM using I2C, SD card interface us							CO4	
Unit-V	ARM Cortex Processors						Period	ls: 9	
system design. applications, ne	RM CORTEX series, improvem CORTEX A, CORTEX M, CO ed of operating system in de opment for ARM Cortex, Surve iods: 45 Tutorial Periods:	ORTEX R veloping c ey of COR	process complex	ors seri applicat based	ies, vers ions in e controlle	ions, fea embedde rs, its fea	atures an ed systen	id n,CO5 id	
1. F. Vahio Wiley In	d and T. Givargis, "Embedded dia Pvt. Ltd., 2002.	•	esign: A	Unified	Hardwar	e/Softwa	re Introdu	uction",	
	Das, "Architecture, Programmin		-f! · ·	4 I -	D			D = =1 =	

Reference Books

- 1. Andrew Sloss, Dominic Symes, Chris Wright, "ARM System Developer's Guide Designing and Optimizing System Software", ELSEVIER
- 2. Joseph Yiu, "The Definitive Guide to the ARM Cortex-M", Newness, ELSEVIER
- 3. Embedded Systems: Real-Time Interfacing to ARM Cortex-M Microcontrollers,2014, Jonathan W Valvano CreateSpace publications ISBN: 978-1463590154.

Web References

- 1. LPC 214x User manual (UM10139): www.nxp.com
- 2. LPC 17xx User manual (UM10360): www.nxp.com
- 3. ARM architecture reference manual: www.arm.com
- 4. http://processors.wiki.ti.com/index.php/HandsOn_Training_for_TI_Embedded_Processors
- 5. http://processors.wiki.ti.com/index.php/MCU_Day_Internet_of_Things_2013_Workshop

COs/POs/PSOs Mapping

COs	Program Outcomes (POs)						Program S	es (PSOs)	
003	PO1	PO2	PO3	PO4	PO5	PO6	PSO1	PSO2	PSO3
1	3	3	3	3	3	-	3	2	-
2	3	3	3	3	3	-	3	2	-
3	3	3	3	3	3	-	3	2	-
4	3	3	3	3	3	-	3	2	-
5	3	3	3	3	3	-	3	2	-

Correlation Level: 1 - Low, 2 - Medium, 3 - High

Evaluation Method

		Contir	nuous Asse	ssment Marks (End Semester	Total	
Assessment	CAT CAT		Model	Assignment*	Attendance	Examination (ESE)	Marks
	1	2	Exam	Assignment	Attenuance	Marks	Walks
Marks	10		15	10	5	60	100

Department		ECE	Progr	amme: N	I.Tech. V				
Semester		First	Cou	irse Cate PE	gory Cod	e: *En	d Seme	ster Exa TE	m Type:
Course Code		P23VEE105	F	Periods/W	/eek	Credit		ximum N	larks
			L	T	P	С	CAM	ESE	TM
Course Name		Analog IC Design	3	0	0	3	40	60	100
Prerequisite		Basic Electri	cal Circuits, S	ignals an	d System	s, Analo	g Circuit	S	
		mpletion of the course	e, the student	s will be	able to				apping st Level
	CO1	Design amplifiers to m	neet user spec	ifications				k	(3
Course	CO2	Analyze the frequency	/ and noise pe	rformanc	e of amp	ifiers		k	(4
Outcome	CO3	Design and analyze fe	edback ampli	fiers and	one stag	e op amp	S	٢	(4
	CO4	Design and analyze tv	wo stage op ar	nps				۲	K 4
	CO5	Design and analyze devices	current mirro	ors and	current s	sinks wi	h MOS	k	(4
Unit- I	Sina	le Stage Amplifiers						Period	ds: 9
	ation, v	I and Cascode Amplifie roltage swing, high gain			SR, nois	e, gain,	BW, ICI	MR and	CO1
Miller effect, Cascode and	associ d Differ	Frequency and Noise ation of poles with node ential Amplifier stages, Differential Amplifiers	Characterist	ics of Ar response	of CS, C				
Miller effect, Cascode and	associ d Differ oise in	ation of poles with node ential Amplifier stages, Differential Amplifiers.	e Characterist es, frequency statistical cha	ics of Ar response racteristic	of CS, C cs of nois			ollower,	CO2
Miller effect, Cascode and amplifiers, no Unit- III Properties a operational a	associ d Differ oise in Feed and typ amplifie	ation of poles with node ential Amplifier stages, Differential Amplifiers. back And Single Stag bes of negative feedbar or performance parame	e Characterist es, frequency statistical cha e Operationa ack circuits, ters, single sta	ics of Ar response racteristic I Amplific effect of age Op A	of CS, C cs of nois ers loading Amps, two	e, noise in feedl p-stage (in Single back ne Dp Amp	ollower, e Stage Perioc etworks,	CO2
Miller effect, Cascode and amplifiers, no Unit- III Properties a operational a range limitat	associ d Differ oise in Feed and typ amplifie ions, ga	ation of poles with node ential Amplifier stages, Differential Amplifiers. back And Single Stag wes of negative feedba or performance parame ain boosting, slew rate,	e Characterist es, frequency statistical cha e Operationa ack circuits, ters, single st power supply	ics of Ar response racteristic I Amplifi effect of age Op A rejection,	of CS, C cs of nois ers loading Amps, two noise in	e, noise in feedl o-stage (Op Amp	in Single back ne Dp Amp	ollower, e Stage Period etworks, s, input	CO2 ds: 9 CO3
Miller effect, Cascode and amplifiers, n Unit- III Properties a operational a range limitat Unit- IV	associ d Differ oise in Feed and typ amplifie ions, ga Stab	ation of poles with node ential Amplifier stages, Differential Amplifiers. back And Single Stag wes of negative feedba or performance parame ain boosting, slew rate, ility And Frequency Co	e Characterist es, frequency statistical cha e Operationa ack circuits, ters, single sta power supply ompensation	ics of Ar response racteristic I Amplific effect of age Op A rejection, of Two S	of CS, C cs of nois ers loading Amps, two noise in Stage Am	e, noise in feedt o-stage (Op Amp: oplifier	in Single back ne Dp Amp s.	ollower, e Stage Period etworks, s, input Period	CO2 ds: 9 CO3
Miller effect, Cascode and amplifiers, no Unit- III Properties a operational a range limitat Unit- IV Analysis Of And Using C And Compe	associ d Differ oise in Feed and typ amplificions, ga Stab Two St Cascod ensation	ation of poles with node ential Amplifier stages, Differential Amplifiers. back And Single Stag bes of negative feedbar or performance parame ain boosting, slew rate, ility And Frequency C a age Op Amp – Two Stage e Second Stage, Multip n Of Two Stage Op	e Characterist es, frequency i statistical cha e Operationa ack circuits, ters, single sta power supply ompensation age Op Amp S ble Systems,	ics of Ar response racteristic I Amplifie effect of age Op A rejection, of Two S Single Sta Phase Ma	of CS, C cs of nois ers loading Amps, two noise in Stage Am age CMC argin, Fre	e, noise in feed o-stage (Op Amp oplifier S CS as equency	in Single back ne Dp Amp s. Secone Comper	e Stage Period etworks, s, input Period d Stage nsation,	CO2 ds: 9 CO3
Miller effect, Cascode and amplifiers, no Unit- III Properties a operational a range limitat Unit- IV Analysis Of And Using O	associ d Differ oise in Feed and typ amplifie ions, ga Stab Two St Cascod ensation on Tecl	ation of poles with node ential Amplifier stages, Differential Amplifiers. back And Single Stag bes of negative feedbar or performance parame ain boosting, slew rate, ility And Frequency C a age Op Amp – Two Stage e Second Stage, Multip n Of Two Stage Op	e Characterist es, frequency i statistical cha e Operationa ack circuits, ters, single sta power supply ompensation age Op Amp S ble Systems,	ics of Ar response racteristic I Amplifie effect of age Op A rejection, of Two S Single Sta Phase Ma	of CS, C cs of nois ers loading Amps, two noise in Stage Am age CMC argin, Fre	e, noise in feed o-stage (Op Amp oplifier S CS as equency	in Single back ne Dp Amp s. Secone Comper	e Stage Period etworks, s, input Period d Stage nsation,	CO2 ds: 9 CO3 ds: 9 CO4
Miller effect, Cascode and amplifiers, no Unit- III Properties a operational a range limitat Unit- IV Analysis Of And Using O And Compe Compensatio Unit- V Current sink current source	associ d Differ oise in Feed and typ amplifici ions, ga Stab Two St Cascod ensation on Tech Banc s and s ce, des indepe	ation of poles with node ential Amplifier stages, Differential Amplifiers. back And Single Stag bes of negative feedbar ain boosting, slew rate, aility And Frequency Co age Op Amp – Two Sta e Second Stage, Multip n Of Two Stage Op nniques. Igap References ources, current mirrors ign of high swing casco ndent references, PTAT	e Characterist es, frequency i statistical cha e Operationa ack circuits, ters, single sta power supply ompensation age Op Amp S ole Systems, I o Amps, Slev , Wilson curre ode sink, curre T and CTAT current	ics of Ar response racteristic I Amplifie effect of age Op A rejection, of Two S Single Sta Phase Ma wing In nt source ent amplifi urrent gen	of CS, C cs of nois ers loading Amps, two noise in Stage Am age CMC argin, Fre Two Stage , Widlar of iers, supp	e, noise in feed o-stage (Op Amp plifier S CS as equency age Op current s oly indep constant	in Single back ne Dp Amp s. Second Comper Amps, ource, c endent l -gm bias	e Stage Period tworks, s, input Period d Stage nsation, Other Period cascode biasing,	CO2 ds: 9 CO3 ds: 9 CO4 ds: 9 CO5
Miller effect, Cascode and amplifiers, nu Unit- III Properties a operational a range limitat Unit- IV Analysis Of And Using C And Compe Compensatio Unit- V Current sink current sourd temperature Lecture Pe	associ d Differ oise in Feed and typ amplifici ions, ga Stab Two St Cascod ensation on Tech Banc s and s ce, des indepe	ation of poles with node ential Amplifier stages, Differential Amplifiers. back And Single Stag bes of negative feedbar ain boosting, slew rate, aility And Frequency Co age Op Amp – Two Sta e Second Stage, Multip n Of Two Stage Op nniques. Igap References ources, current mirrors ign of high swing casco ndent references, PTAT	e Characterist es, frequency i statistical cha e Operationa ack circuits, ters, single sta power supply ompensation age Op Amp S ole Systems, I o Amps, Slev , Wilson curre ode sink, curre T and CTAT current	ics of Ar response racteristic I Amplifie effect of age Op A rejection, of Two S Single Sta Phase Ma wing In nt source ent amplifi urrent gen	of CS, C cs of nois ers loading Amps, two noise in Stage Am age CMC argin, Fre Two Sta e, Widlar of iers, supp meration,	e, noise in feed o-stage (Op Amp plifier S CS as equency age Op current s oly indep constant	in Single back ne Dp Amp s. Second Comper Amps, ource, c endent l -gm bias	e Stage Period etworks, s, input Period d Stage nsation, Other Period eascode biasing, sing.	CO2 ds: 9 CO3 ds: 9 CO4 ds: 9 CO5
Miller effect, Cascode and amplifiers, nu Unit- III Properties a operational a range limitat Unit- IV Analysis Of And Using O And Compe Compensatio Unit- V Current sink current source temperature Lecture Po extbooks 1. Jacob	associ d Differ oise in Feed and typ amplifie ions, ga Stab Two St Cascod ensation on Tecl Banc s and s ce, des indepe eriods:	ation of poles with node ential Amplifier stages, Differential Amplifiers. back And Single Stag bes of negative feedba er performance paramet ain boosting, slew rate, ility And Frequency C age Op Amp – Two Stage age Op Amp – Two Stage second Stage, Multip n Of Two Stage Op nniques. Igap References ources, current mirrors ign of high swing casco ndent references, PTAT 45 Tutorial Perio "CMOS: Circuit Design	Characterist es, frequency istatistical cha e Operationa ack circuits, ters, single sta power supply ompensation age Op Amp S be Systems, I bo Amps, Slev , Wilson curre de sink, curre f and CTAT cu bods: - F	ics of Ar response racteristic I Amplifie effect of age Op A rejection, of Two S Single Sta Phase Ma wing In Int source ent amplifier urrent gen Practical	of CS, C cs of nois ers loading Amps, two noise in Stage Am age CMC argin, Fre Two Sta e, Widlar of iers, supp neration, Periods: on, Wiley	e, noise in feed o-stage (Op Amp oplifier S CS as equency age Op current s oly indep constant	in Single back ne Dp Amp s. Second Comper Amps, ource, c endent l ogn bias Tota	e Stage Period etworks, s, input Period d Stage nsation, Other Period cascode biasing, sing. I Period	CO2 ds: 9 CO3 ds: 9 CO4 ds: 9 CO5 s: 45
Miller effect, Cascode and amplifiers, nu Unit- III Properties a operational a range limitat Unit- IV Analysis Of And Using O And Compe Compensatio Unit- V Current sink current source temperature Lecture Po extbooks 1. Jacob 2. Willey	associ d Differ oise in Feed and typ amplifie ions, ga Stab Two St Cascod ensation on Tecl Banc s and s ce, des indepe eriods: Baker M.C. S	ation of poles with node ential Amplifier stages, Differential Amplifiers. back And Single Stag bes of negative feedbar r performance paramet ain boosting, slew rate, ility And Frequency Co age Op Amp – Two Stage age Op Amp – Two Stage second Stage, Multip n Of Two Stage Op nniques. Igap References ources, current mirrors ign of high swing casco ndent references, PTAT 45 Tutorial Perio	Characterist es, frequency istatistical cha e Operationa ack circuits, ters, single sta power supply ompensation age Op Amp S be Systems, I bo Amps, Slev , Wilson curre de sink, curre f and CTAT cu bods: - F	ics of Ar response racteristic I Amplifie effect of age Op A rejection, of Two S Single Sta Phase Ma wing In Int source ent amplifier urrent ger Practical	of CS, C cs of nois ers loading Amps, two noise in Stage Am age CMC argin, Fre Two Sta e, Widlar of iers, supp neration, Periods: on, Wiley	e, noise in feed o-stage (Op Amp oplifier S CS as equency age Op current s oly indep constant	in Single back ne Dp Amp s. Second Comper Amps, ource, c endent l ogn bias Tota	e Stage Period etworks, s, input Period d Stage nsation, Other Period cascode biasing, sing. I Period	CO2 ds: 9 CO3 ds: 9 CO4 ds: 9 CO5 s: 45
Miller effect, Cascode and amplifiers, nu Unit- III Properties a operational a range limitat Unit- IV Analysis Of And Using C And Compe Compensatio Unit- V Current sink current source temperature Lecture Po extbooks 1. Jacob 2. Willey Reference Bo 3. Phillip	associ d Differ oise in Feed and typ amplifie ions, ga Stab Two St Cascod ensation on Tech Banc s and s ce, des indepe eriods: Baker M.C. S ooks ad Raza	ation of poles with node ential Amplifier stages, Differential Amplifiers. back And Single Stag bes of negative feedbar or performance paramet ain boosting, slew rate, ility And Frequency C age Op Amp – Two Stage age Op Amp – Two Stage second Stage, Multip n Of Two Stage Op nniques. Igap References ources, current mirrors ign of high swing casco ndent references, PTAT 45 Tutorial Perio "CMOS: Circuit Design Sansen, "Analog Design avi, "Design of Analog C polar and Mos Analog In n, Douglas R .Holberg, "	Characterist es, frequency i statistical cha e Operationa ack circuits, ters, single sta power supply ompensation age Op Amp s ole Systems, I o Amps, Slev , Wilson curre ode sink, curre T and CTAT cr ods: - I n, Layout, And Essentials", S Cmos Integrate	ics of Ar response racteristic I Amplifie effect of age Op A rejection, of Two S Single Sta Phase Ma wing In Int source ent amplifier arrent gen Practical Simulati Springer, 2 d Circuits uit Design	of CS, C cs of nois ers loading Amps, two noise in Stage Am age CMC argin, Fre Two Sta e, Widlar of iers, supp neration, Periods: on, Wiley 2006.	e, noise in feedl o-stage (Op Amp S CS as equency age Op current s oly indep constant - IEEE P	in Single back ne Op Amp s. Second Comper Amps, ource, c endent l gm bias Tota ress, 3 rd ill, 2001	e Stage Period etworks, s, input Period d Stage nsation, Other Period cascode biasing, sing. I Period Edition,	CO2 ds: 9 CO3 ds: 9 CO4 ds: 9 CO5 s: 45

Web References

- 1. https://archive.nptel.ac.in/courses/117/106/117106030/
- 2. https://onlinecourses.nptel.ac.in/noc22_ee15/preview
- 3. https://onlinecourses.nptel.ac.in/noc22_ee34/preview
- 4. https://www.nptelvideos.com/course.php?id=525
- 5. https://www.udemy.com/topic/analog-circuits/

COs/POs/PSOs Mapping

COs		Prog	gram Out	comes (F	Program Specific Outcomes (PSOs)				
	PO1	PO2	PO3	PO4	PO5	PO6	PSO1	PSO2	PSO3
1	2	-	-	2	-	-	1	-	-
2	2	-	-	2	-	-	1	-	-
3	2	-	-	2	-	-	1	-	-
4	2	-	-	2	-	-	1	-	-
5	2	-	-	2	2	-	1	-	-

Correlation Level: 1 - Low, 2 - Medium, 3 – High

Evaluation Method

			Contir	nuous Asse	ssment Marks (CAM)	End Semester	Total
Assessment		CAT	CAT	Model	Assignment*	Attendance	Examination (ESE)	Marks
		4	2	Exam	Assignment	Allenuance	Marks	iviai kā
		1	2	Exam			IVId KS	

Department	ECE	Progra	amme: N	I.Tech. V	LSI &	ES		
Semester	II	Cours	se Categ PE	ory Code	e: *End	d Semes	ter Exar TE	n Type
Course Code	P23VEE312	_	riods/We	T _ 1	Credit	<u>1</u>	imum M	T
Course	Design for Verification Using UVM	L 3	Т 0	Р 0	C 3	CAM 40	ESE 60	тм 100
Name				<u> </u>		<u> </u>		L
Prerequisite	Nil							
	On completion of the course, the stud						BT Ma (Highes	t Level
_	CO1 Understand the basic concepts of		ethodolo	gies UVN	M		K	_
Course	CO2 Build actual verification compone	nts.					K	3
Outcome	CO3 Generate the register layer classe	es.					K	3
	CO4 Code testbenches using UVM.						K	3
	CO5 Understand advanced peripheral	bus tes	tbenche	s.			K	3
Unit-I	Introduction						Period	s: 9
	he Typical UVM Testbench Architectur FLM) -Overview- TLM, TLM-1, and ion							CO1
Unit-II	Developing Reusable Verification C	ompon	ents				Period	s: 9
	ata Items for Generation - Transaction			nents - (Creatin	g the D		
Instantiating	e Sequencer - Connecting the Drive Components- Creating the Agent - C	reating	the Env					CO2
Unit-III	anaging of Test-Implementing Checks an UVM Using Verification Component		rage				Period	c· 9
Creating a T -Verification	op-Level Environment- Instantiating Veri Component Configuration - Creating a Fests- Virtual Sequences- Checking for I	fication nd Sele	ecting a	User-De	fined T	est - Ci	asses reating	CO3
Unit-IV	UVM Using the Register Layer Class	ses					Period	s: 9
	egister Layer Classes - Back-Door Acce 'erification Environment- Integrating a Re							CO4
Unit-V	Assignment in Testbenches						Period	s: 9
Assignment,	APB: Protocol, Test bench Architecture g Sequences, Building Test, Design and				r, Moni	tor, Age		CO5
Lecture P	eriods: 45 Tutorial Periods: -	Pra	actical F	Periods:	-	Total	Periods	
								5:09
extbooks								5: 09
1. The U 2. Chris S	VM Primer, An Introduction to the Univ Spear, Greg Tumbush," System Verilog 1)13.
2. Chris S	VM Primer, An Introduction to the Univ Spear, Greg Tumbush," System Verilog 1 age Features"3rd edition, 2012.)13.

Web References

- 1. https://www.chipverify.com/uvm/uvm-tutorial
- 2. https://verificationguide.com/uvm/uvm-testbench-architecture/
- 3. https://www.udemy.com/course/learn-ovm-uvm/
- 4. https://cse.iitpkd.ac.in/courses/cs5626-PreSilicon-Design-Verification-using-Formal-Property-Verification/
- 5. https://www.cadence.com/en_US/home/training/all-courses/82143.html

* TE – Theory Exam, LE – Lab Exam

COs/POs/PSOs Mapping

COs		Pro	gram Out	comes (F	Program Specific Outcomes (PSOs)				
	PO1	PO2	PO3	PO4	PO5	PO6	PSO1	PSO2	PSO3
1	1	-	1	1	2	-	1	-	-
2	1	-	1	1	2	-	1	-	-
3	1	-	1	1	2	-	1	-	-
4	1	-	1	1	2	1	1	-	-
5	1	-	1	1	2	1	1	-	-

Correlation Level: 1 - Low, 2 - Medium, 3 – High

Evaluation Method

		Contir	nuous Asse	ssment Marks (CAM)	End Semester	Total
Assessment	CAT	CAT	Model	Assignment*	Attendance	Examination (ESE)	Marks
	1 2		Exam			Marks	
Marks	10		15	10	5	60	100

0 +	:			ed systems			1.10	gramme:				
Semester			II			Cours	e Cateo PC		e: *E	nd Seme	ester Exam TE	ι Туре
Course Code			P23VEE	211		Pe	riods/W	eek	Credi	t Ma	ximum Ma	arks
Course Coue			FZJVEE	314		L	Т	Р	С	CAM	ESE	ТМ
Course Name	Tes	ting	and Fault VLSI Cire	Diagnosis cuits	of	3	0	0	3	40	60	100
Prerequisite	To und	ersta	nd the pro	cess of test	gene	ration,	DFT are	chitecture	e and f	ault diag	nosis	
		-		e course, th				able to			BT Maj (Highest	Level
		•		ferent types							K2	2
Course	CO2 (Gene	rate test p	atterns to de	etect	he fau	lt in con	nbination	al circu	uits	Ka	3
Outcome	CO3 (Gene	rate test p	atterns to de	etect	he fau	lt in seq	uential ci	rcuits		Ka	3
	CO4 [Desig	n a circuit	for testabilit	ty						Ka	3
	CO5	nfer 1	the differe	nt measures	s of sy	stem c	liagnosa	able			K2	2
	<u>.</u>											
Unit-I	Fault	Mod	leling and	Simulation	١						Period	s: 9
Defect, errors ault-Modeling simulation- Sta	circuits	for	simulatio	n- Algorithi	ms fo							
Unit-II	Test	Gene	eration of	Combinatio	onal (Circuit	5				Period	s: 9
Algorithms and ATPG algorithm											nbinationa	CO2
Unit-III	Test	Gene	eration of	Sequential	Circu	uits					Period	s: 9
ATPG for sin sequential circu	•	ck s	synchrono	us circuits-	Time	e-Fram	e expa	ansion m	nethod	-Simulati	on based	CO3
Unit-IV			r Testabil								Period	
Festability –Ad egisters- Gene approaches-Bo	eric sca	in-ba	sed desig	n- Classica								
			el Diagno								Period	s: 9
Basic concepts												
combinational based on struct				ns for diag	nosis	- Effe	ct caus	e analys	is- Dia	agnostic	reasoning	CO 5
Lecture Pe				ial Periods:		Pra	ectical I	Periods:	-	Tota	I Periods	: 45
Textbooks												
Signal 2. Liu, Ru 2012.	VLSI Ci ey-wen	rcuits	s", Kluwer	D., "Essenti Academic P Diagnosis of	Publisl	ners, 2	nd Print	ing, 2005	5.	-		
Reference Boo		-								· · · –		
Publish	ing Hou	ise, ′	13th Impre	and Friedma ssion, 2012 – wen wu, X	•							
				n Kaufmanr							Gintootun	
Neb Referenc												
2. https:// 3. https://	nptel.ac archive.	.in/co nptel	ourses/117 l.ac.in/cou	.in/noc20_e 7105137 rses/106/10 tent/storage	3/106	10311		16/				

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COs/POs/PSOs Mapping

COs		Pro	gram Out	comes (F	Program Specific Outcomes (PSOs)				
003	PO1	PO2	PO3	PO4	PO5	PO6	PSO1	PSO2	PSO3
1	3	1	1	-	-	-	1	-	-
2	3	2	1	-	-	-	1	-	-
3	3	2	1	-	-	-	1	-	-
4	3	2	1	-	2	-	1	-	-
5	2	1	1	-	-	-	1	-	-

Correlation Level: 1 - Low, 2 - Medium, 3 - High

Evaluation Method

		Contir	nuous Asse	End Semester	Total		
Assessment	CAT CAT 1 2		Model	Assignment*	Attendance	Examination (ESE)	Marks
			Exam	Assignment	Attenuance	Marks	Walks
Marks	10		15	10	5	60	100